



US011085963B2

(12) **United States Patent**
Whetsel

(10) **Patent No.:** **US 11,085,963 B2**
(45) **Date of Patent:** **Aug. 10, 2021**

(54) **SWITCHING FPI BETWEEN FPI AND RPI FROM RECEIVED BIT SEQUENCE**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 32 days.

(21) Appl. No.: **16/562,602**

(22) Filed: **Sep. 6, 2019**

(65) **Prior Publication Data**

US 2019/0391205 A1 Dec. 26, 2019

Related U.S. Application Data

(62) Division of application No. 16/043,468, filed on Jul. 24, 2018, now Pat. No. 10,459,028, which is a (Continued)

(51) **Int. Cl.**

G01R 31/317 (2006.01)
G01R 31/28 (2006.01)
G01R 31/302 (2006.01)
G01R 31/3185 (2006.01)
G01R 31/3177 (2006.01)

(52) **U.S. Cl.**

CPC ... **G01R 31/31713** (2013.01); **G01R 31/2815** (2013.01); **G01R 31/2884** (2013.01); **G01R 31/3025** (2013.01); **G01R 31/3177** (2013.01); **G01R 31/31703** (2013.01); **G01R 31/31725** (2013.01); **G01R 31/31727** (2013.01); **G01R 31/318558** (2013.01); **G01R 31/2851** (2013.01)

(58) **Field of Classification Search**

CPC G01R 31/3025; G01R 31/318558; G01R 31/3177; G01R 31/2851; G01R 31/2815; G01R 31/31703; G01R 31/31727; G01R 31/31713; G01R 31/31725; G01R 31/2884

See application file for complete search history.

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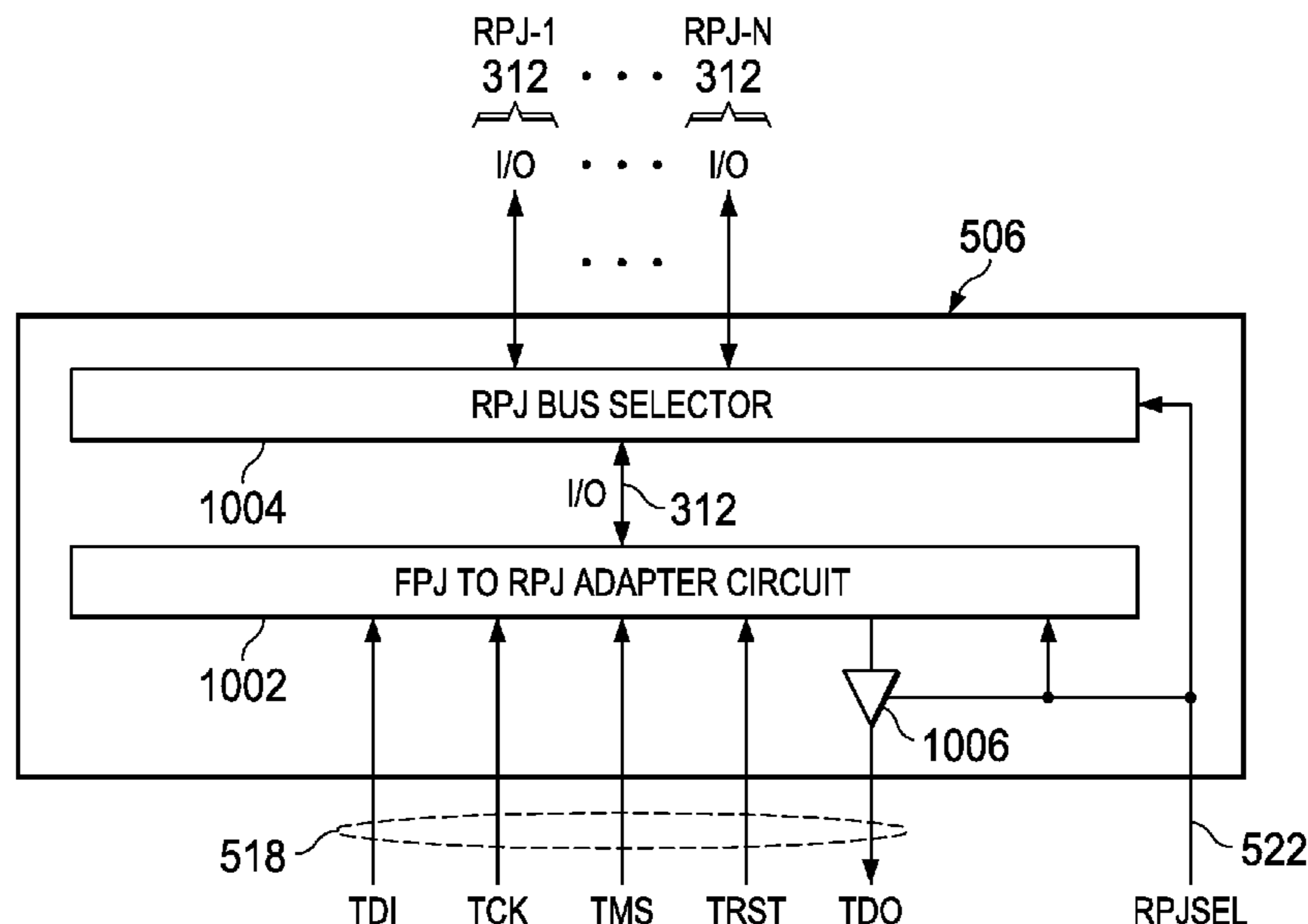
Primary Examiner — Cynthia Britt

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(57) **ABSTRACT**

The disclosure describes a process and apparatus for accessing devices on a substrate. The substrate may include only full pin JTAG devices (504), only reduced pin JTAG devices (506), or a mixture of both full pin and reduced pin JTAG devices. The access is accomplished using a single interface (502) between the substrate (408) and a JTAG controller (404). The access interface may be a wired interface or a wireless interface and may be used for JTAG based device testing, debugging, programming, or other type of JTAG based operation.

28 Claims, 17 Drawing Sheets



Related U.S. Application Data

division of application No. 15/467,485, filed on Mar. 23, 2017, now Pat. No. 10,054,633, which is a division of application No. 15/159,171, filed on May 19, 2016, now Pat. No. 9,645,198, which is a division of application No. 14/815,396, filed on Jul. 31, 2015, now Pat. No. 9,372,230, which is a division of application No. 14/456,125, filed on Aug. 11, 2014, now Pat. No. 9,128,152, which is a division of application No. 13/488,956, filed on Jun. 5, 2012, now Pat. No. 8,839,060, which is a division of application No. 13/078,621, filed on Apr. 1, 2011, now Pat. No. 8,225,157, which is a division of application No. 12/883,629, filed on Sep. 16, 2010, now Pat. No. 7,945,832, which is a division of application No. 11/874,594, filed on Oct. 18, 2007, now Pat. No. 7,818,641.

(60) Provisional application No. 60/829,979, filed on Oct. 18, 2006.

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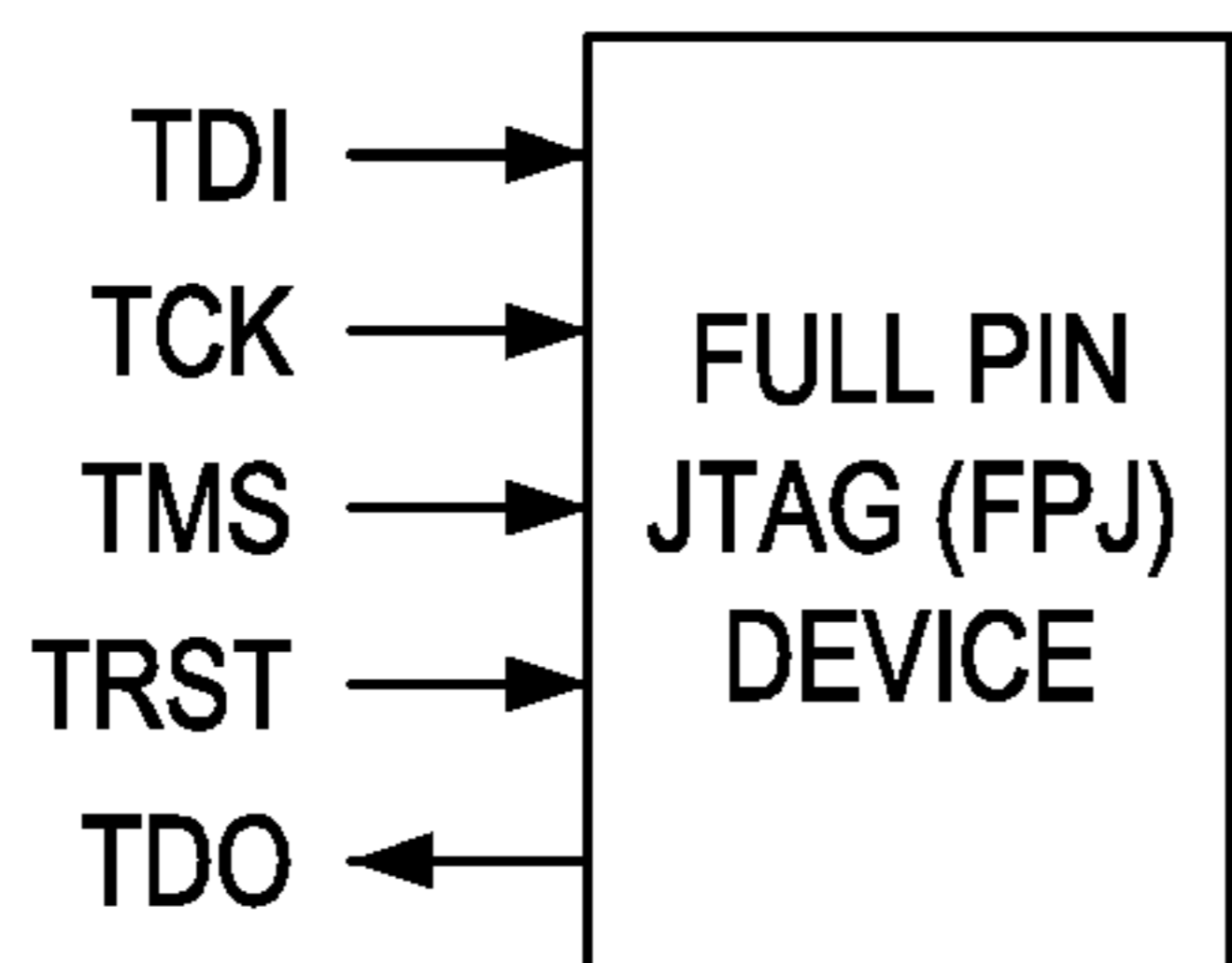


FIG. 1
(PRIOR ART)

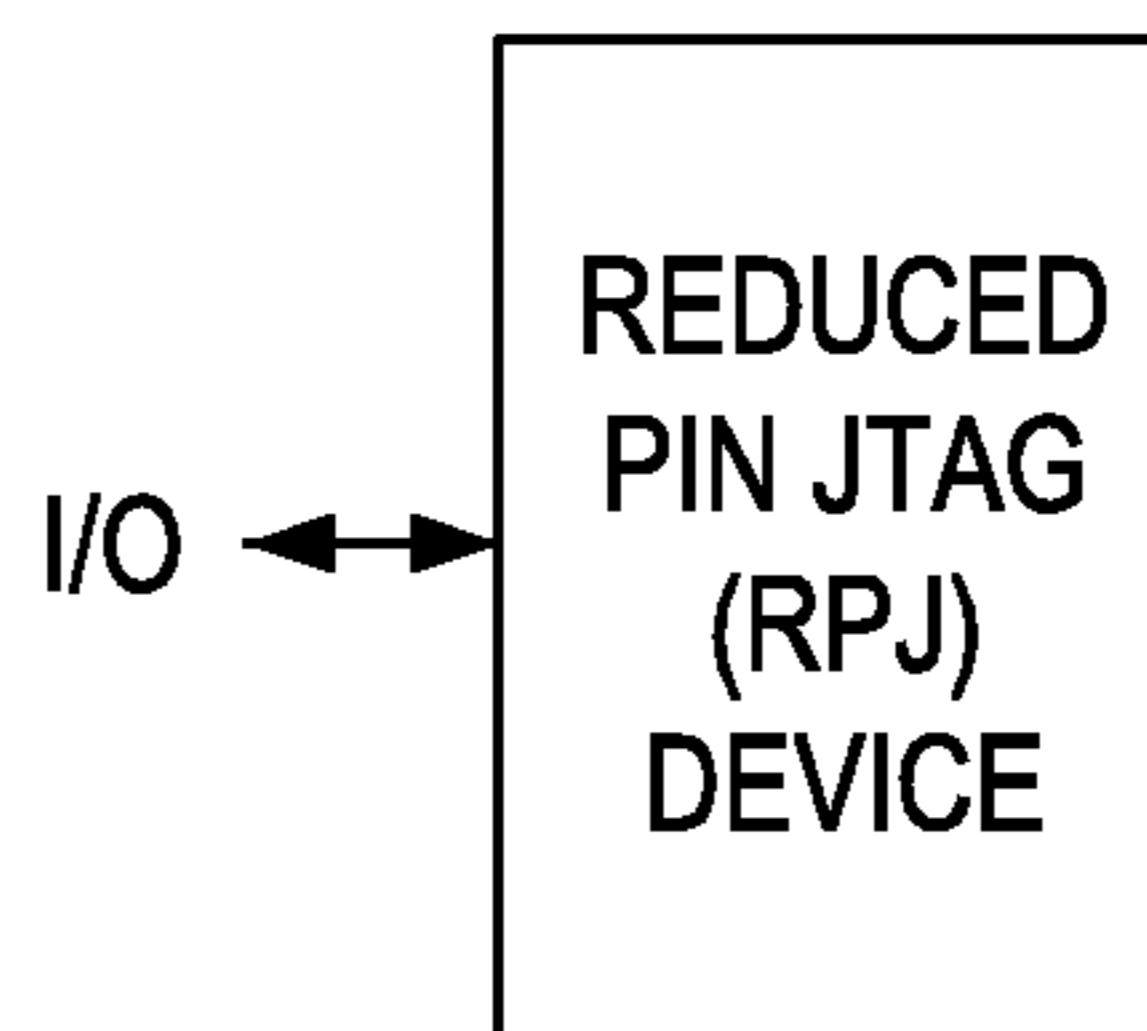


FIG. 2
(PRIOR ART)

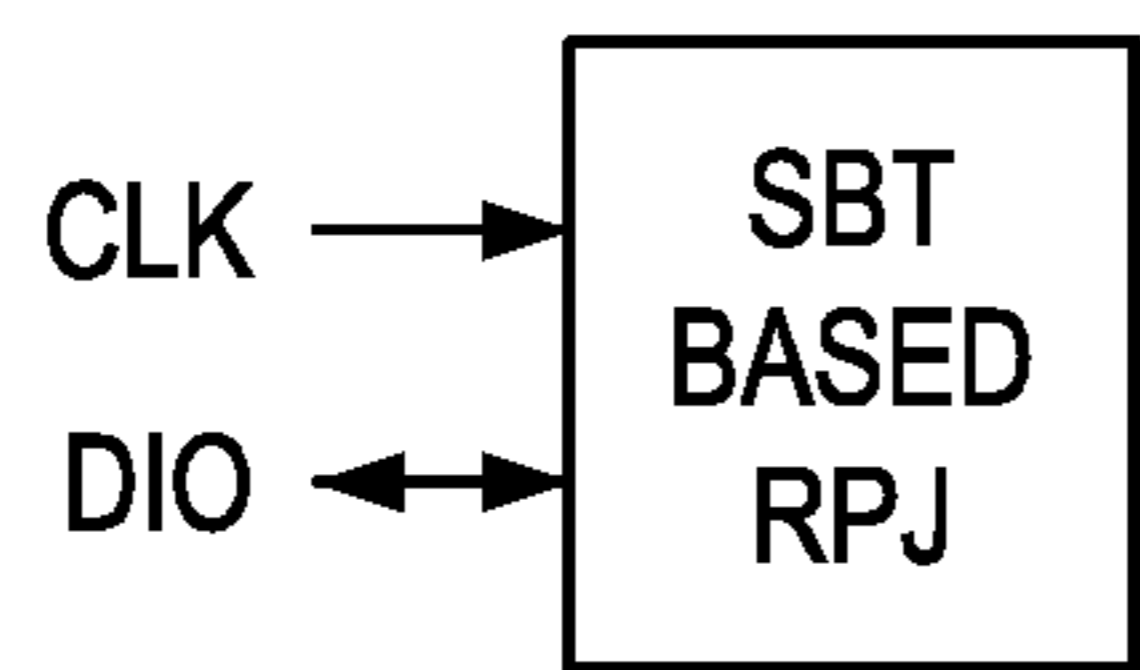


FIG. 2A
(PRIOR ART)

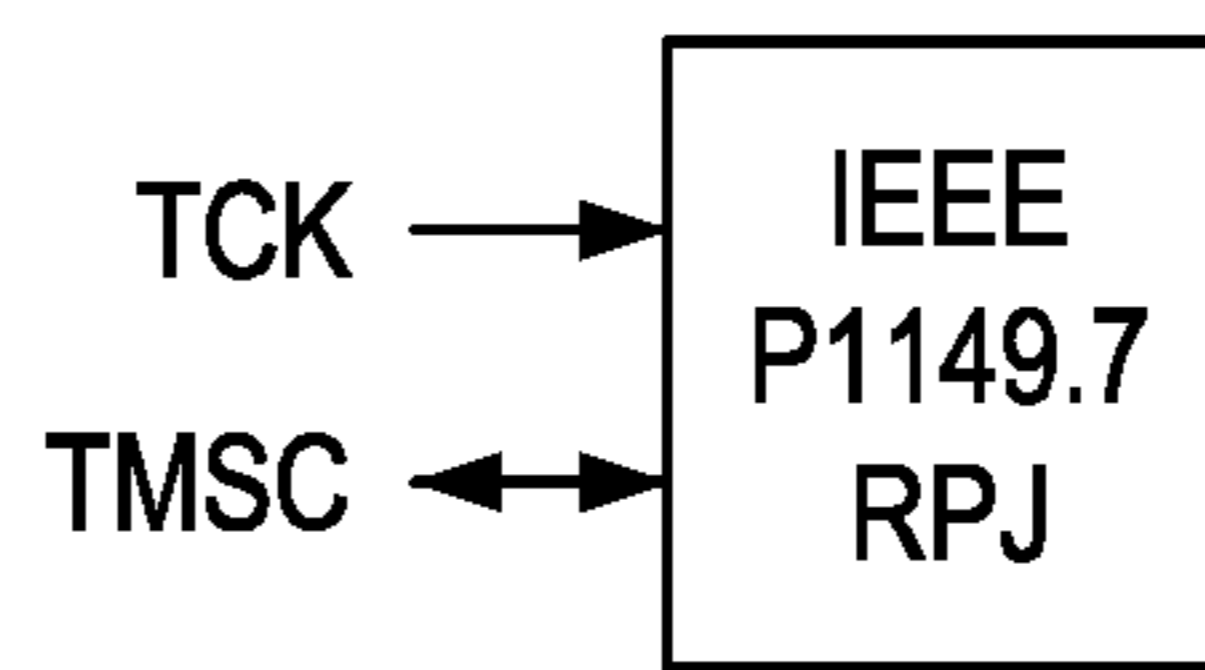


FIG. 2B
(PRIOR ART)

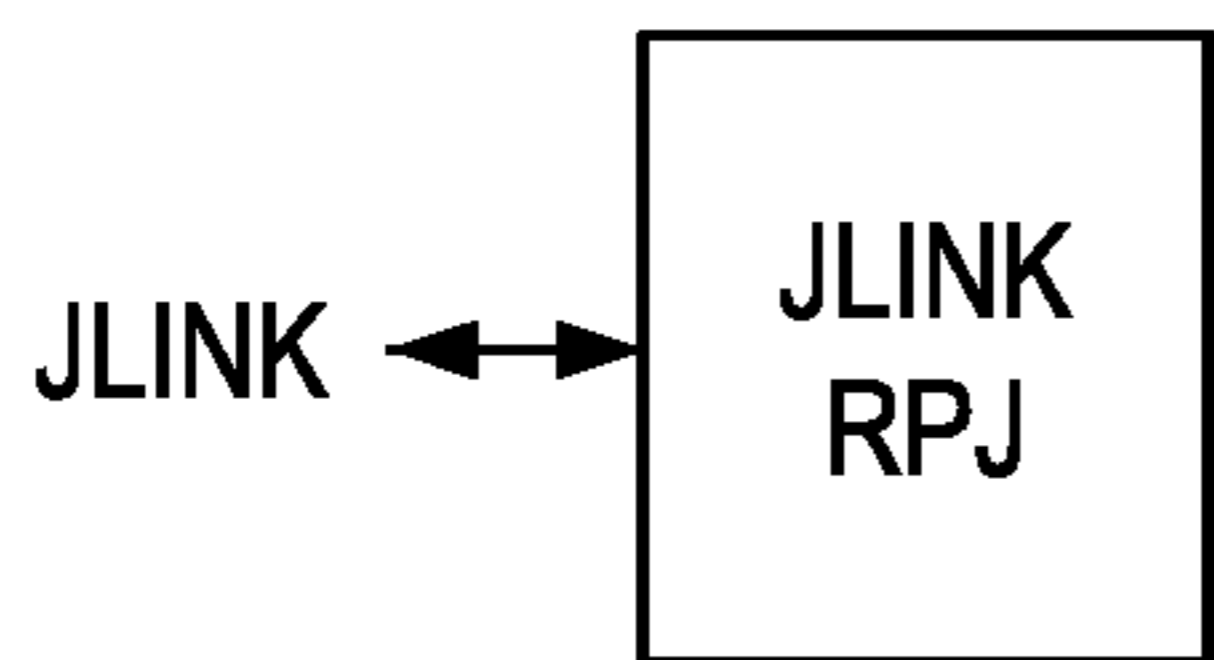


FIG. 2C
(PRIOR ART)

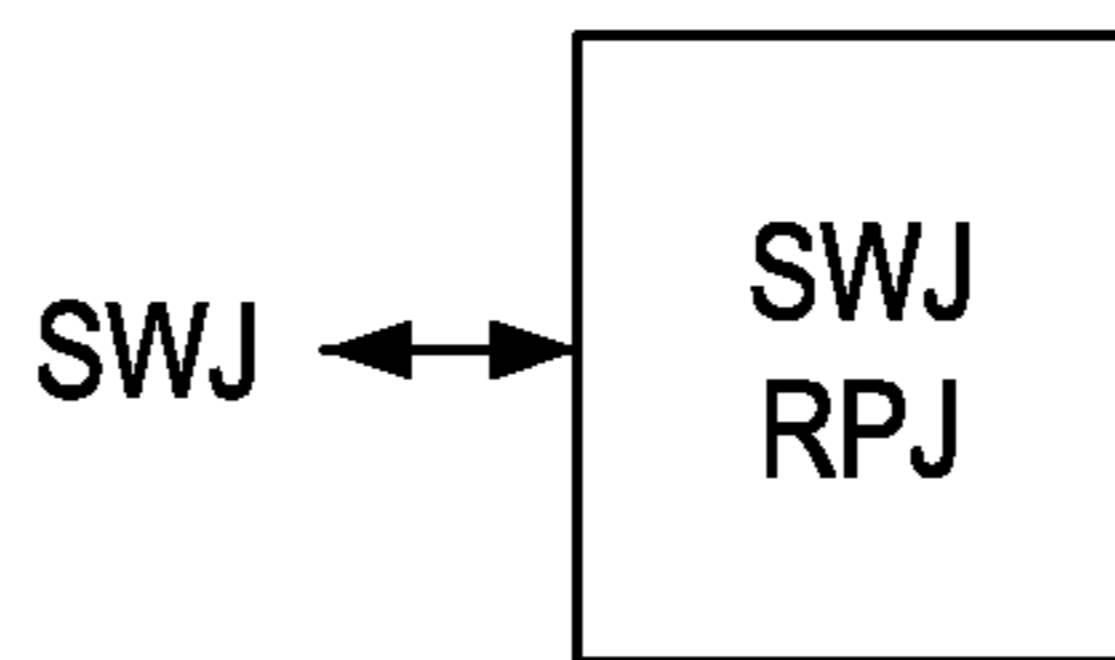


FIG. 2D
(PRIOR ART)

FIG. 3 (PRIOR ART)

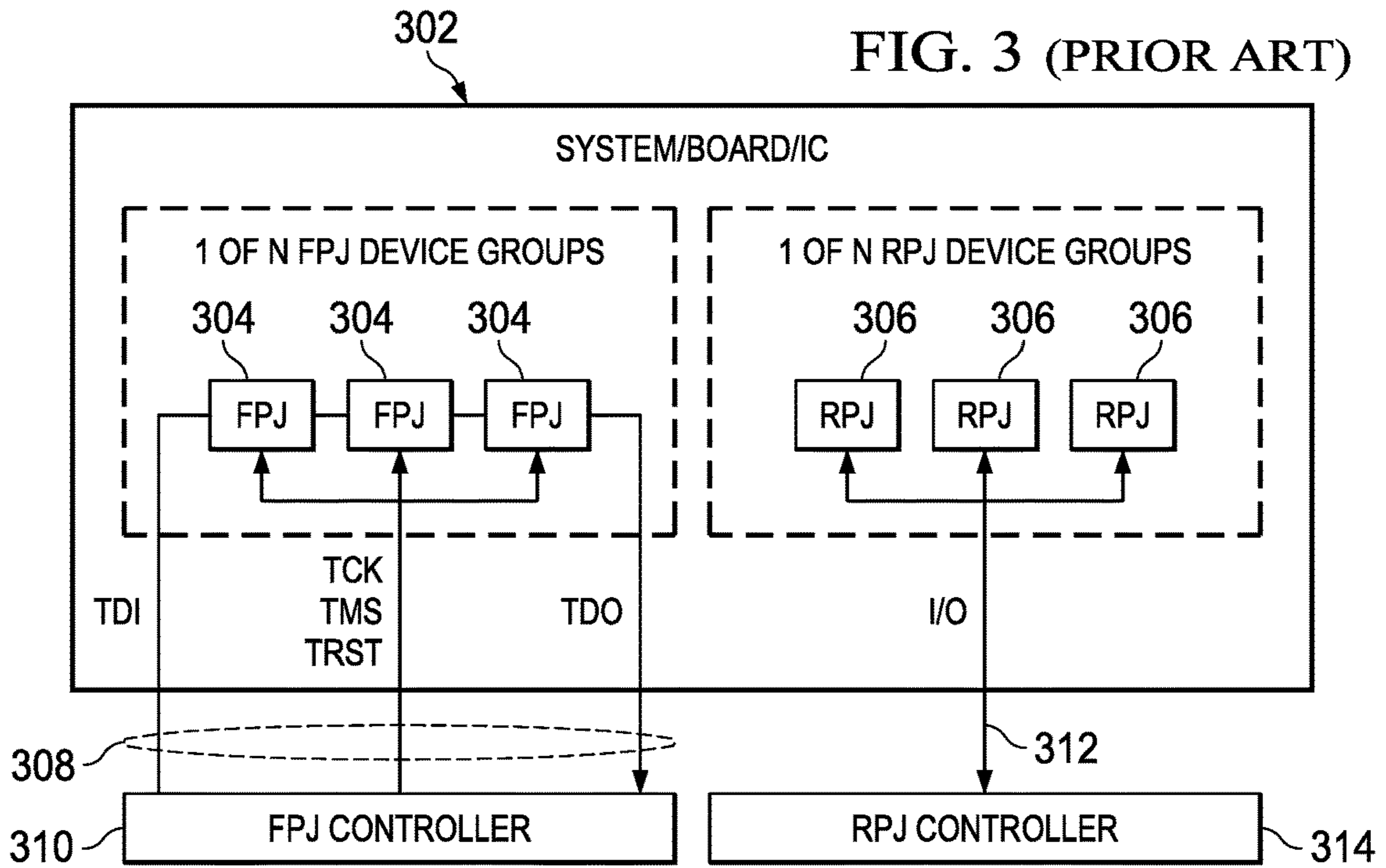
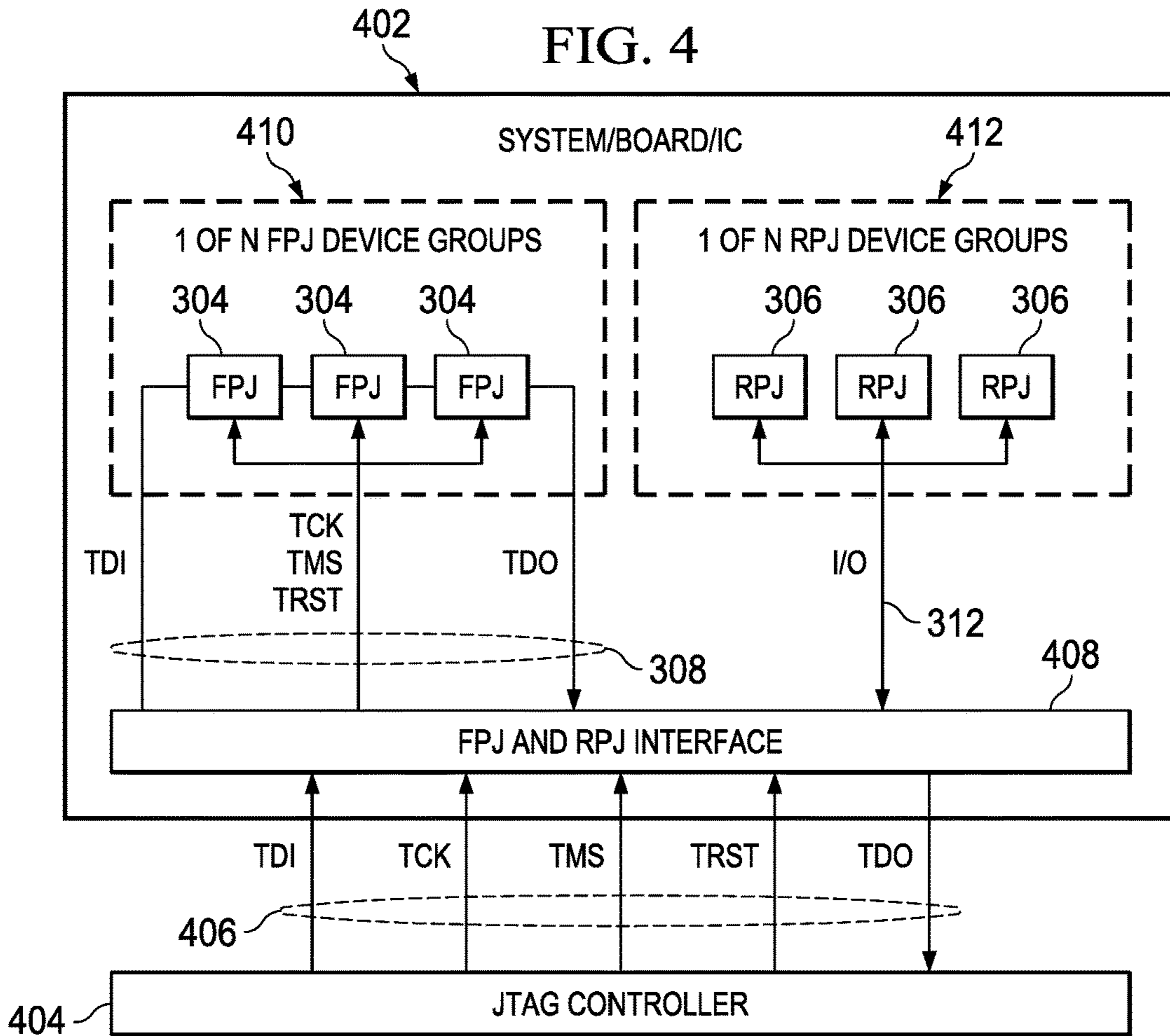


FIG. 4



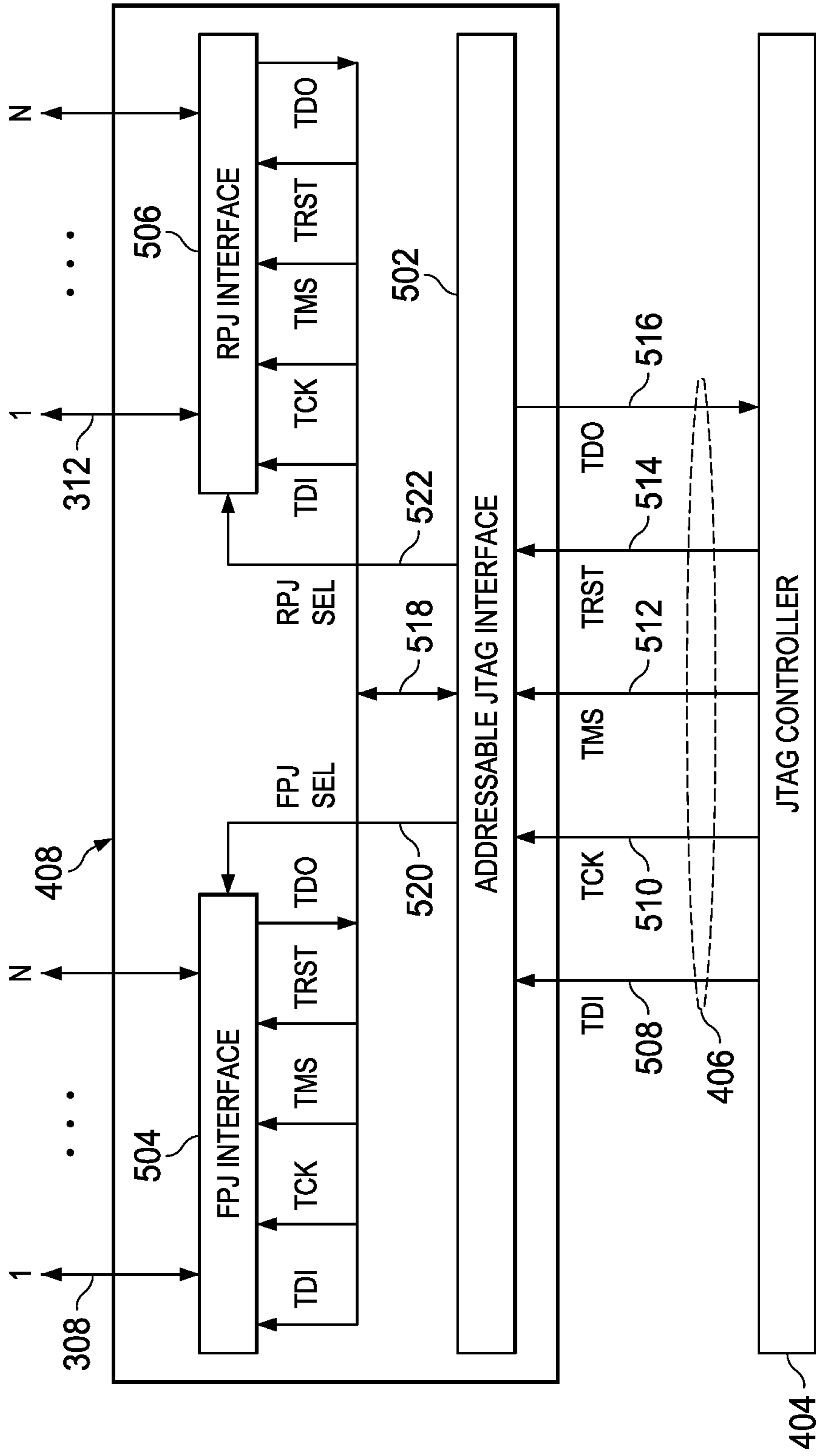


FIG. 5

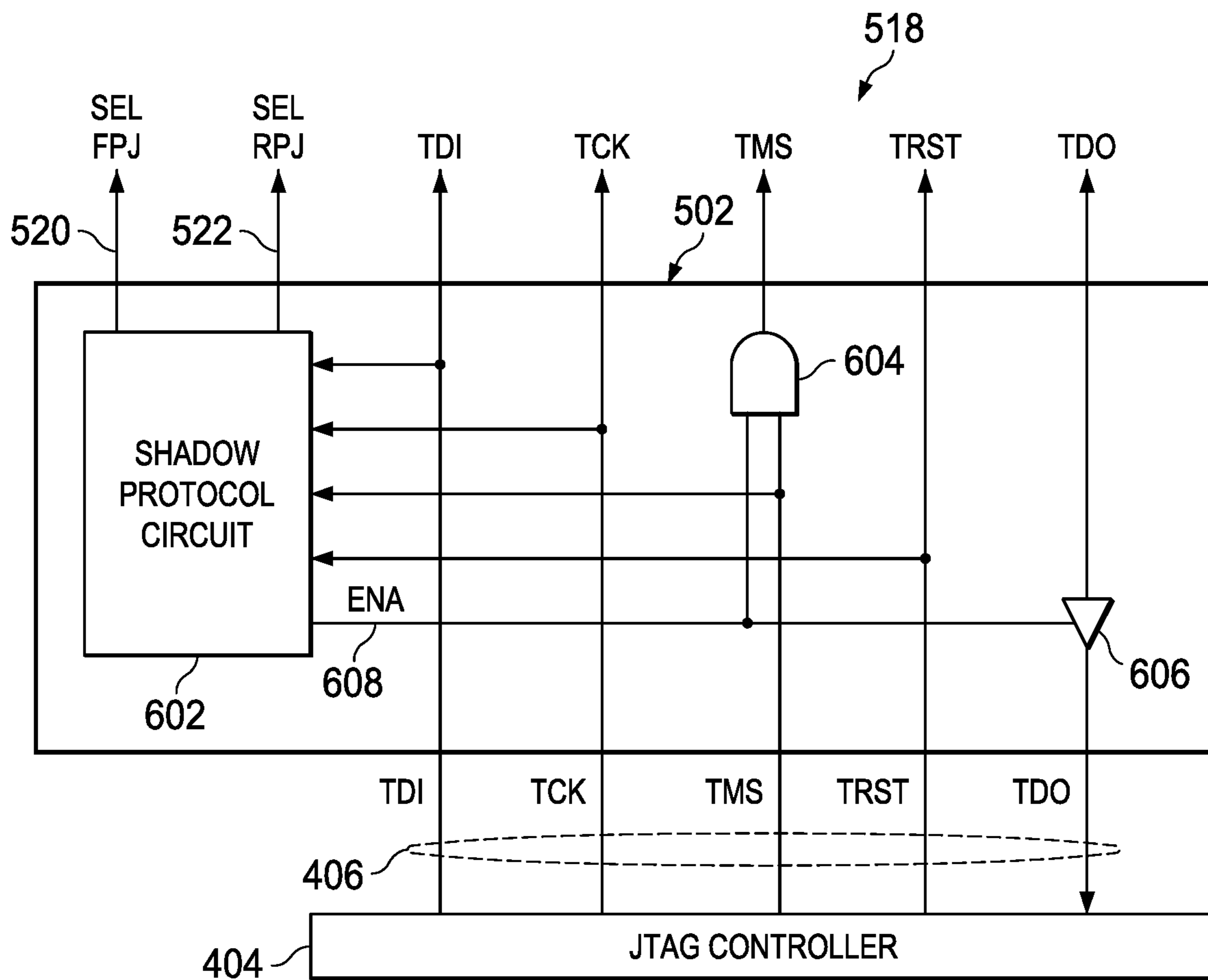


FIG. 6

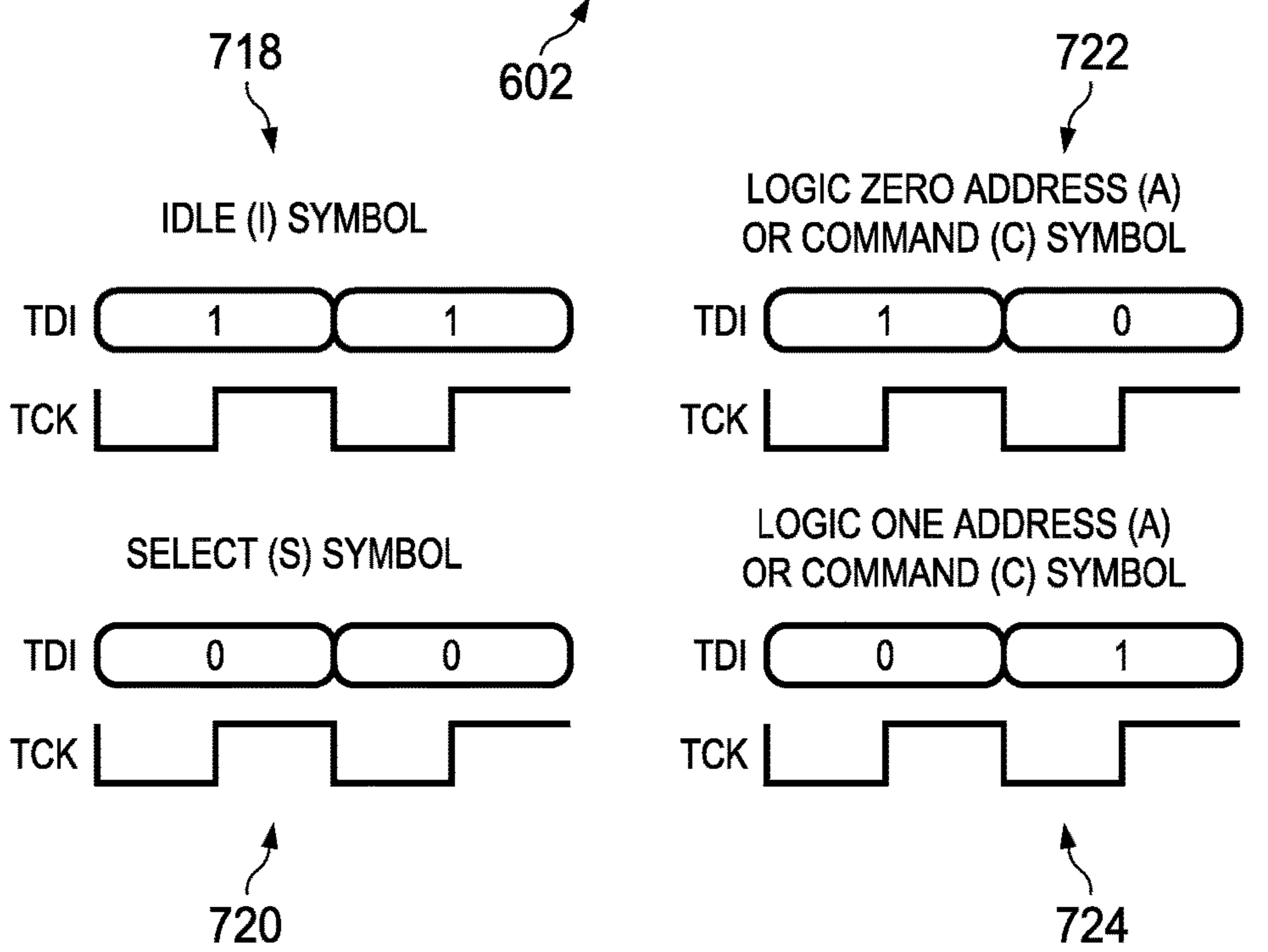
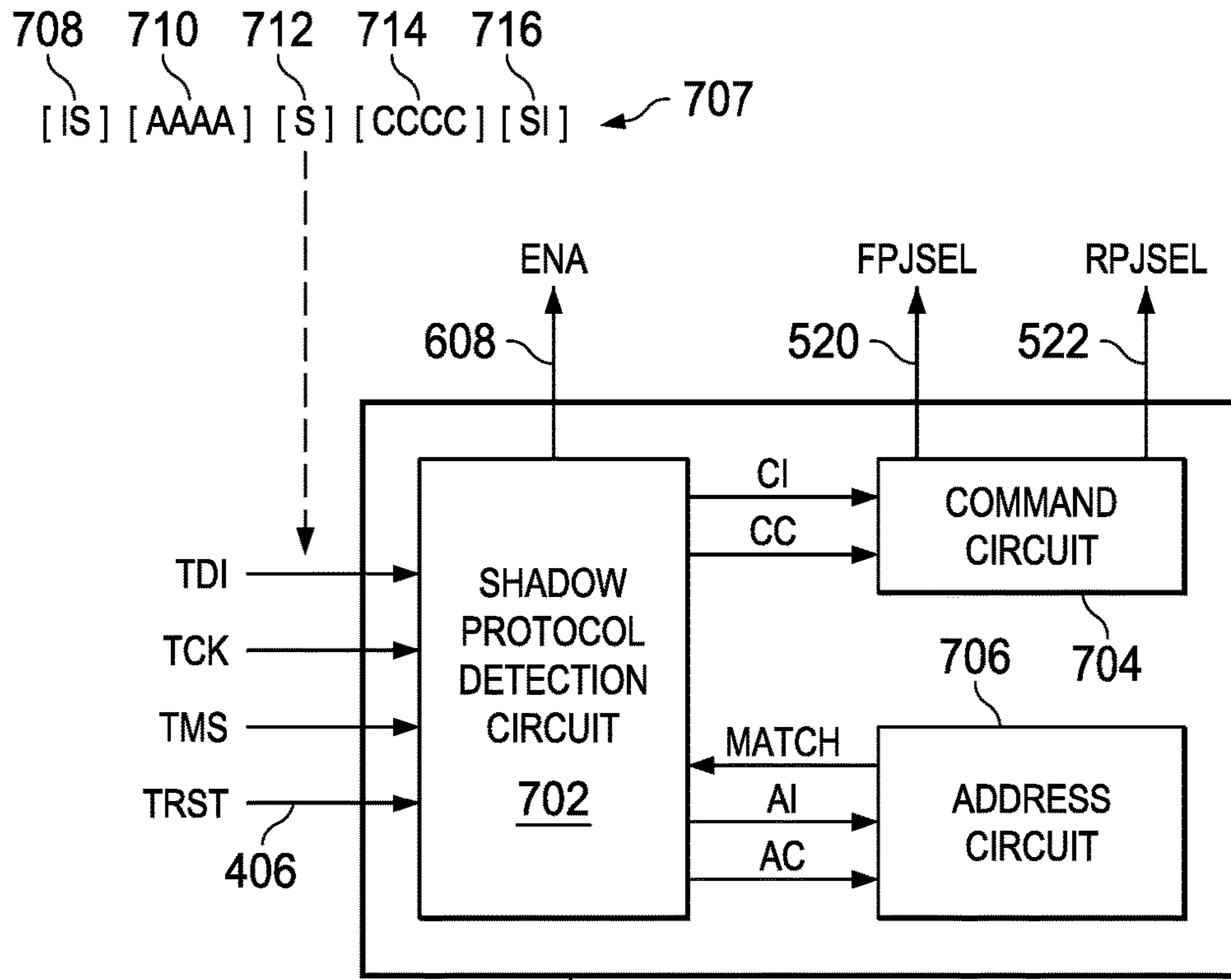


FIG. 7

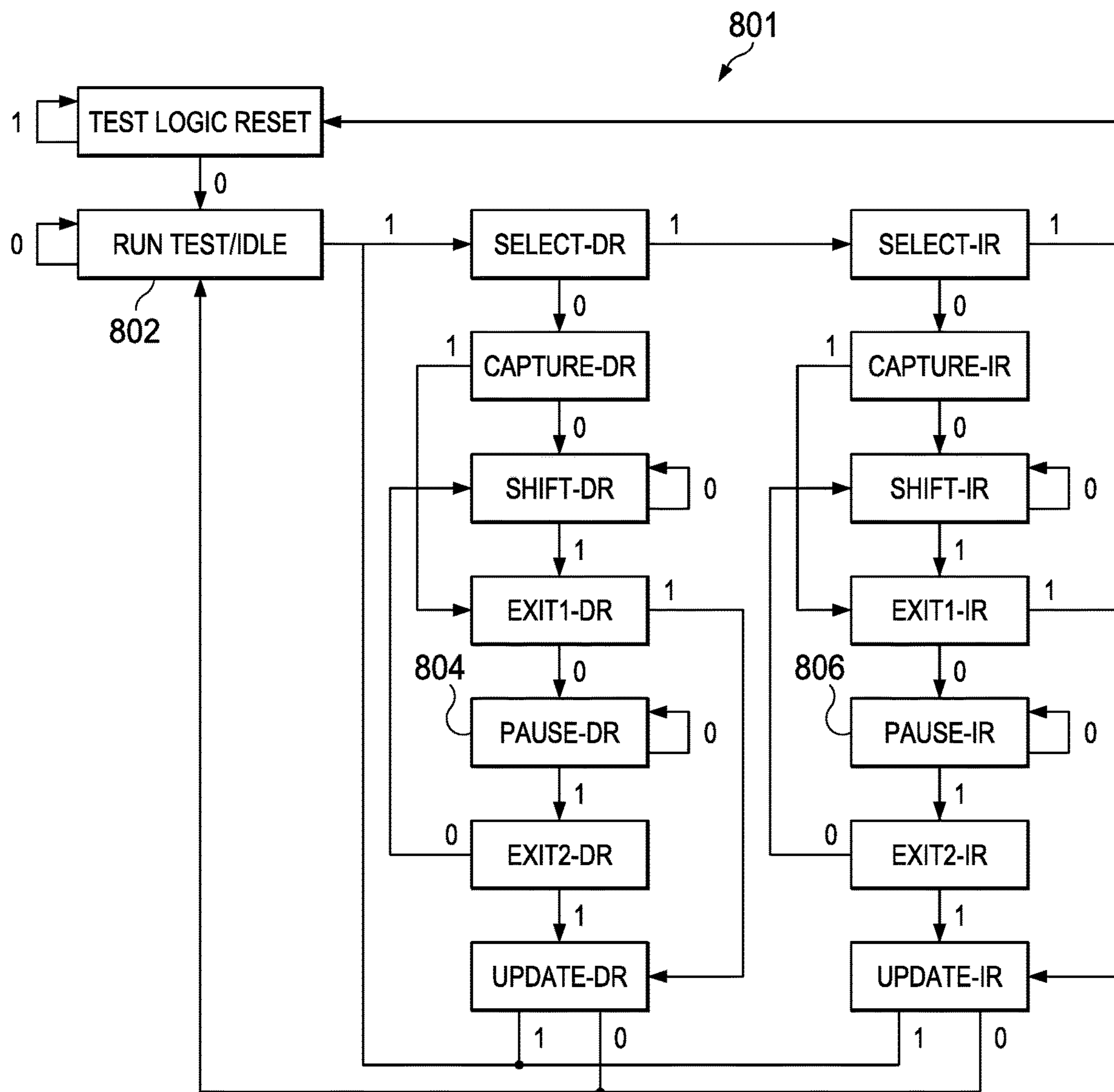


FIG. 8A

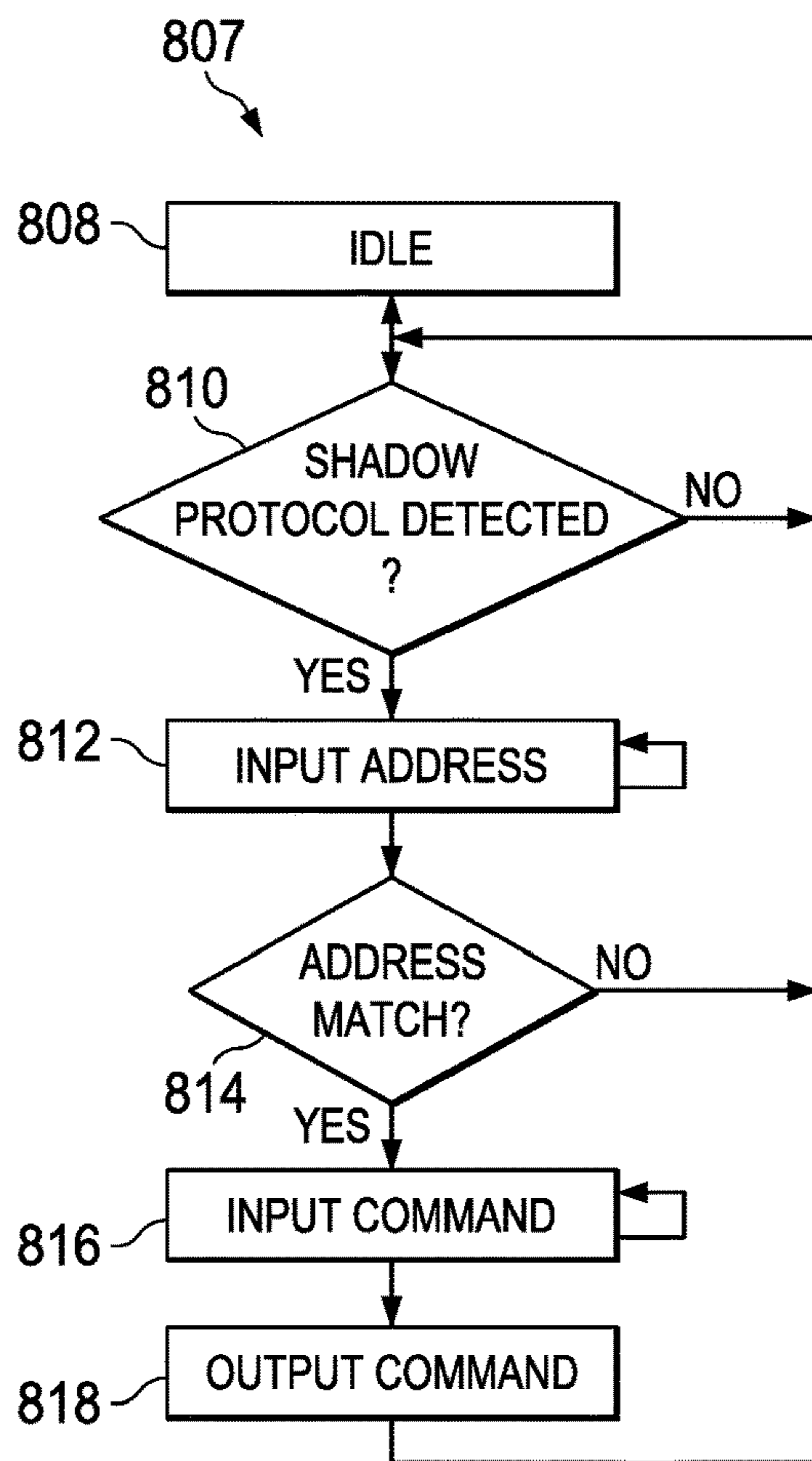


FIG. 8B

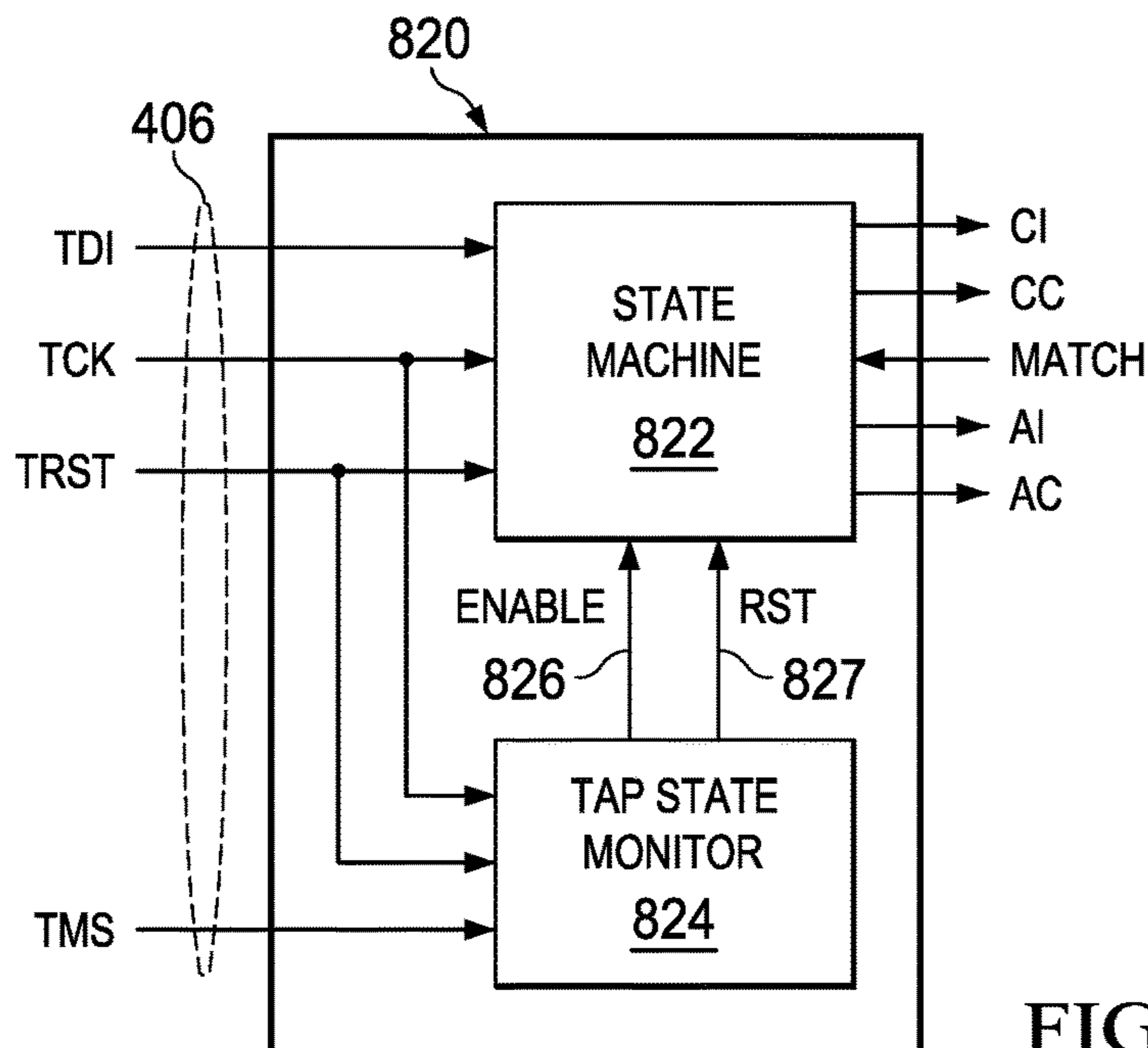


FIG. 8C

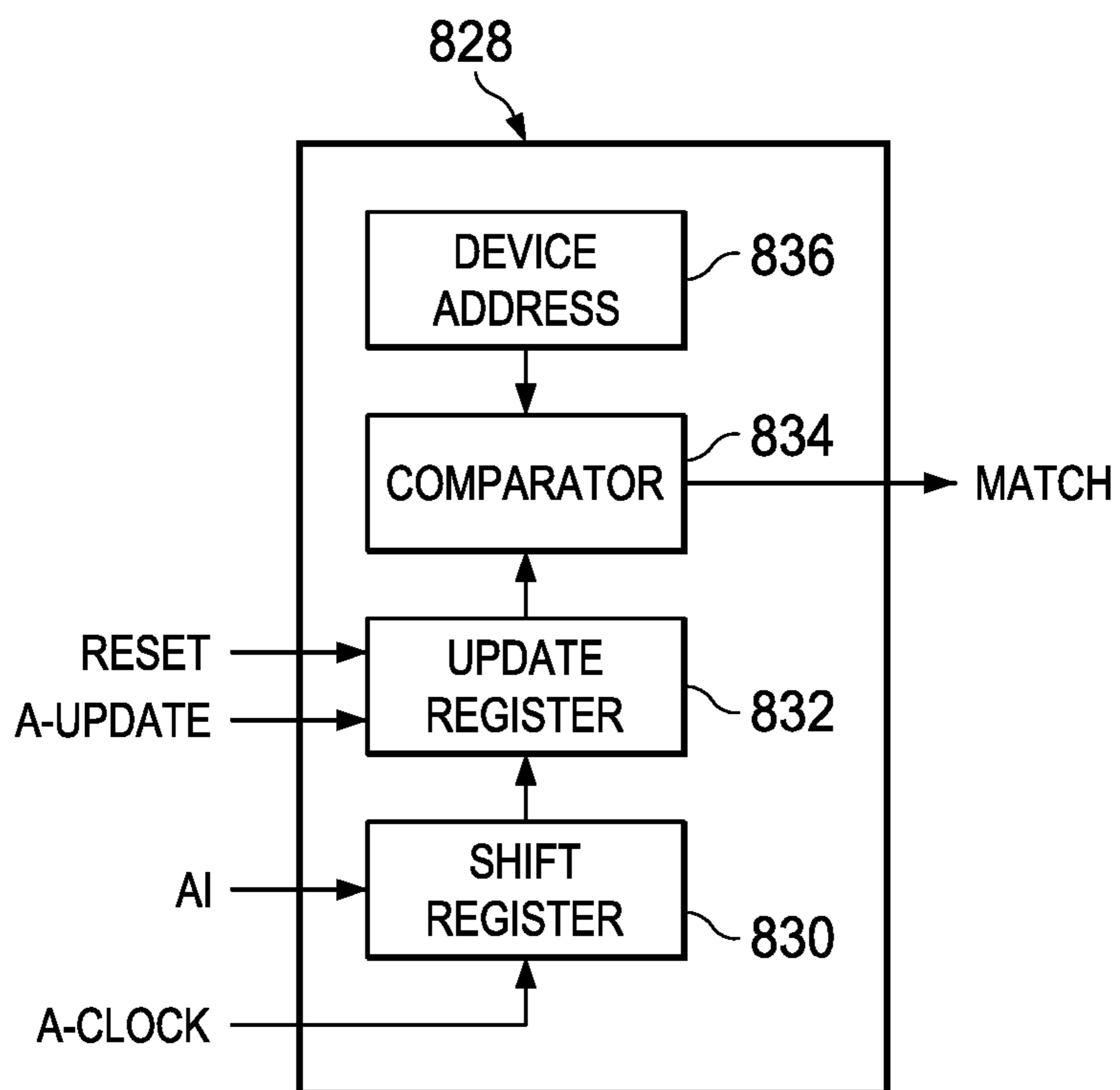


FIG. 8D

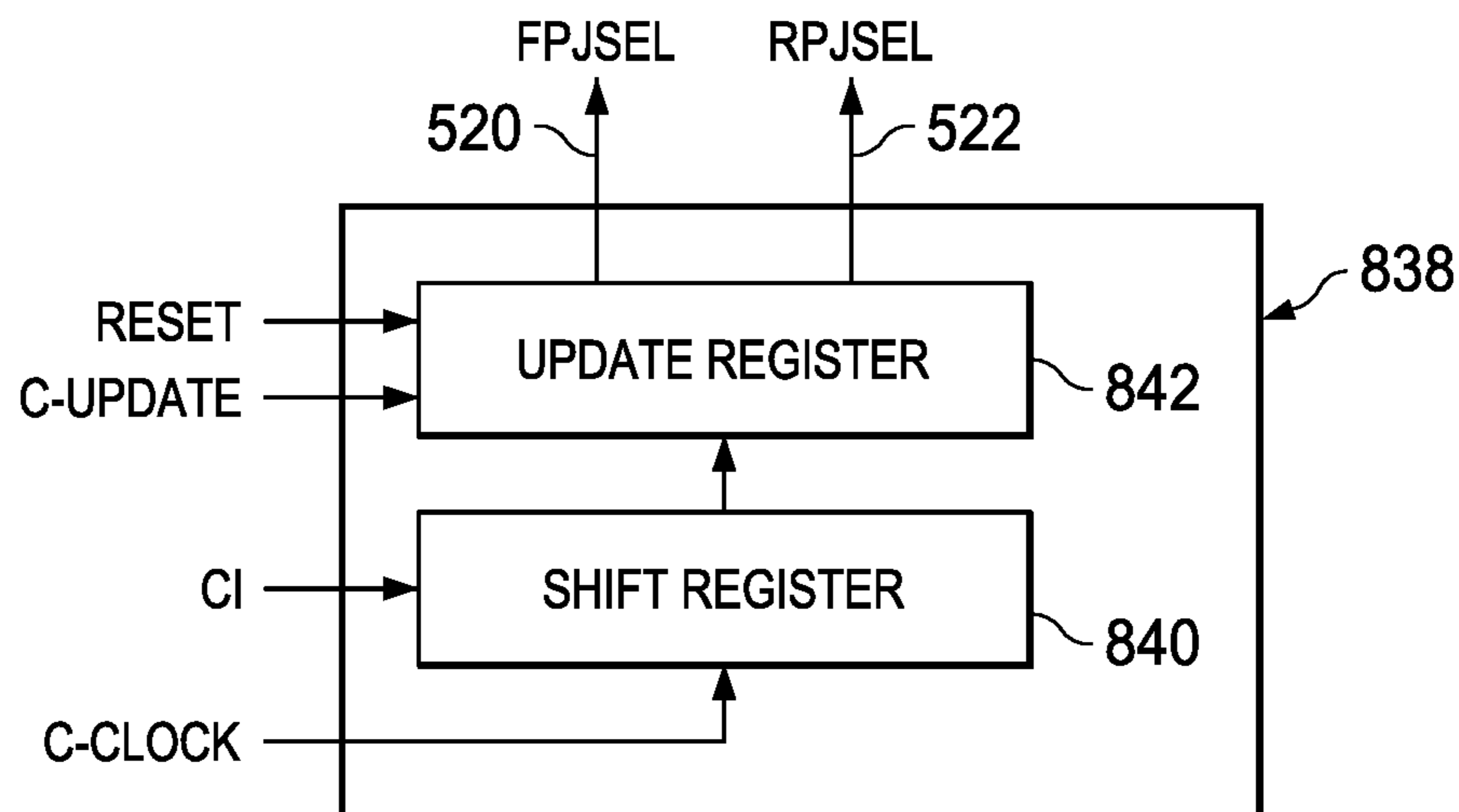


FIG. 8E

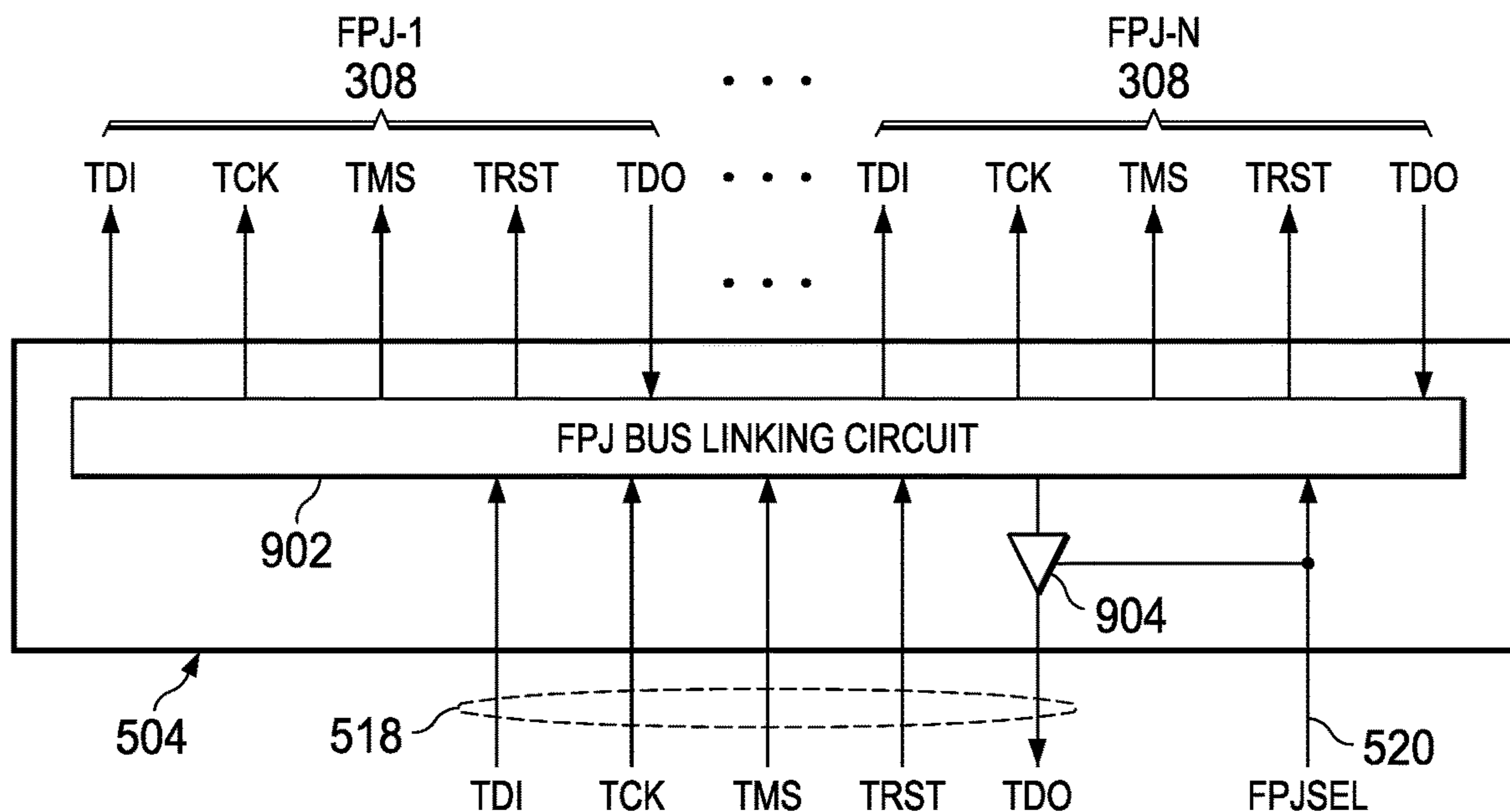


FIG. 9

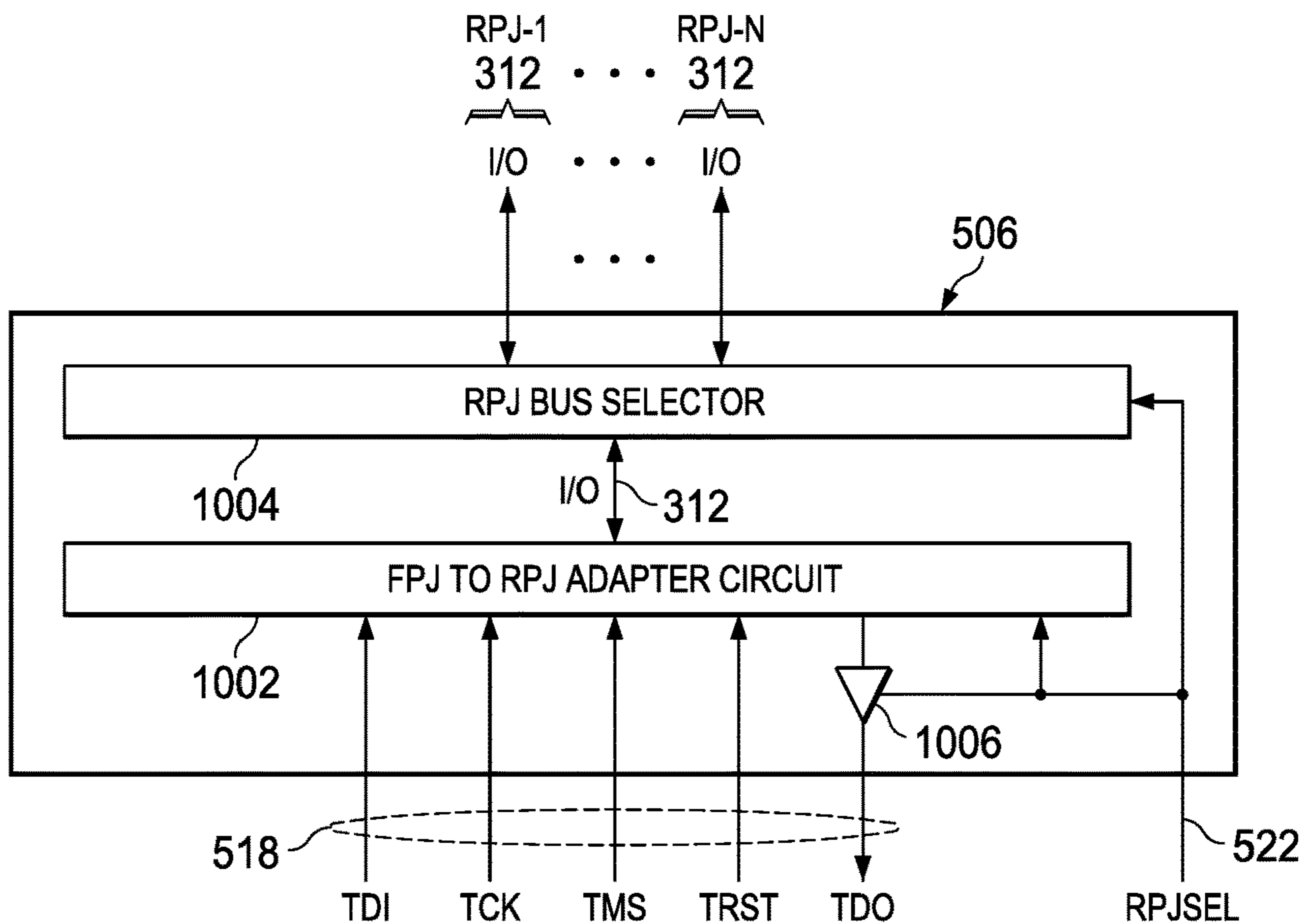
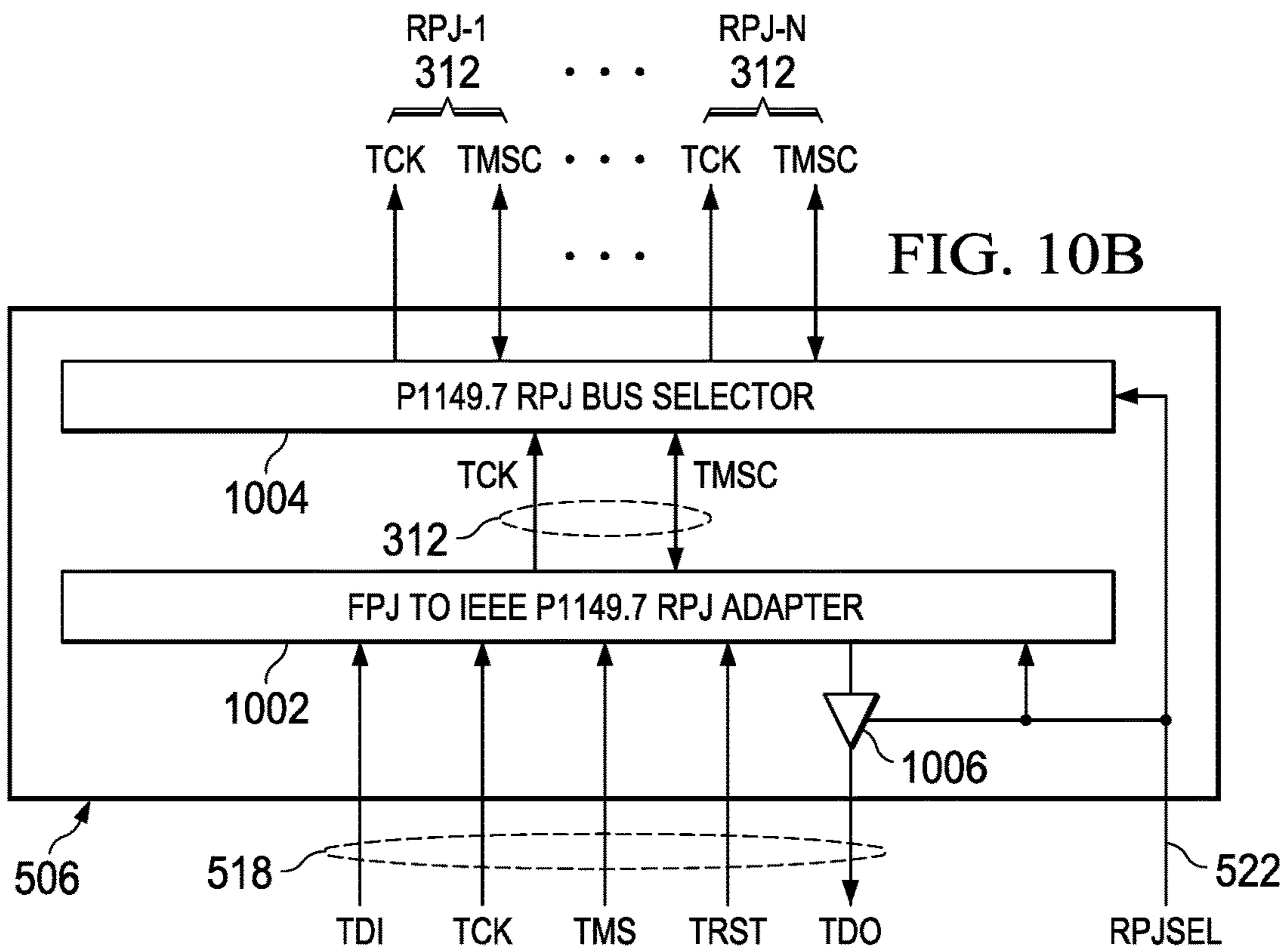
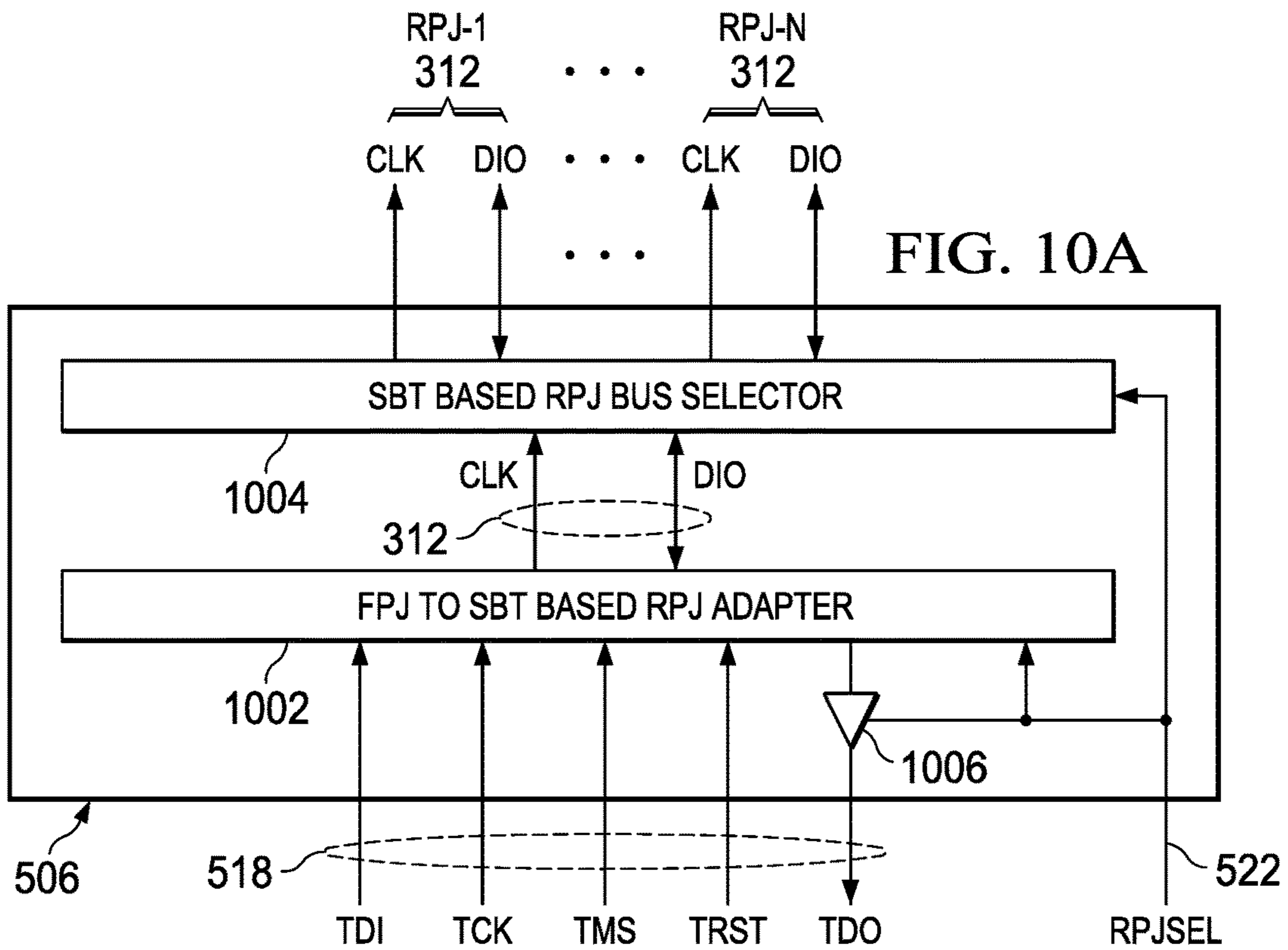
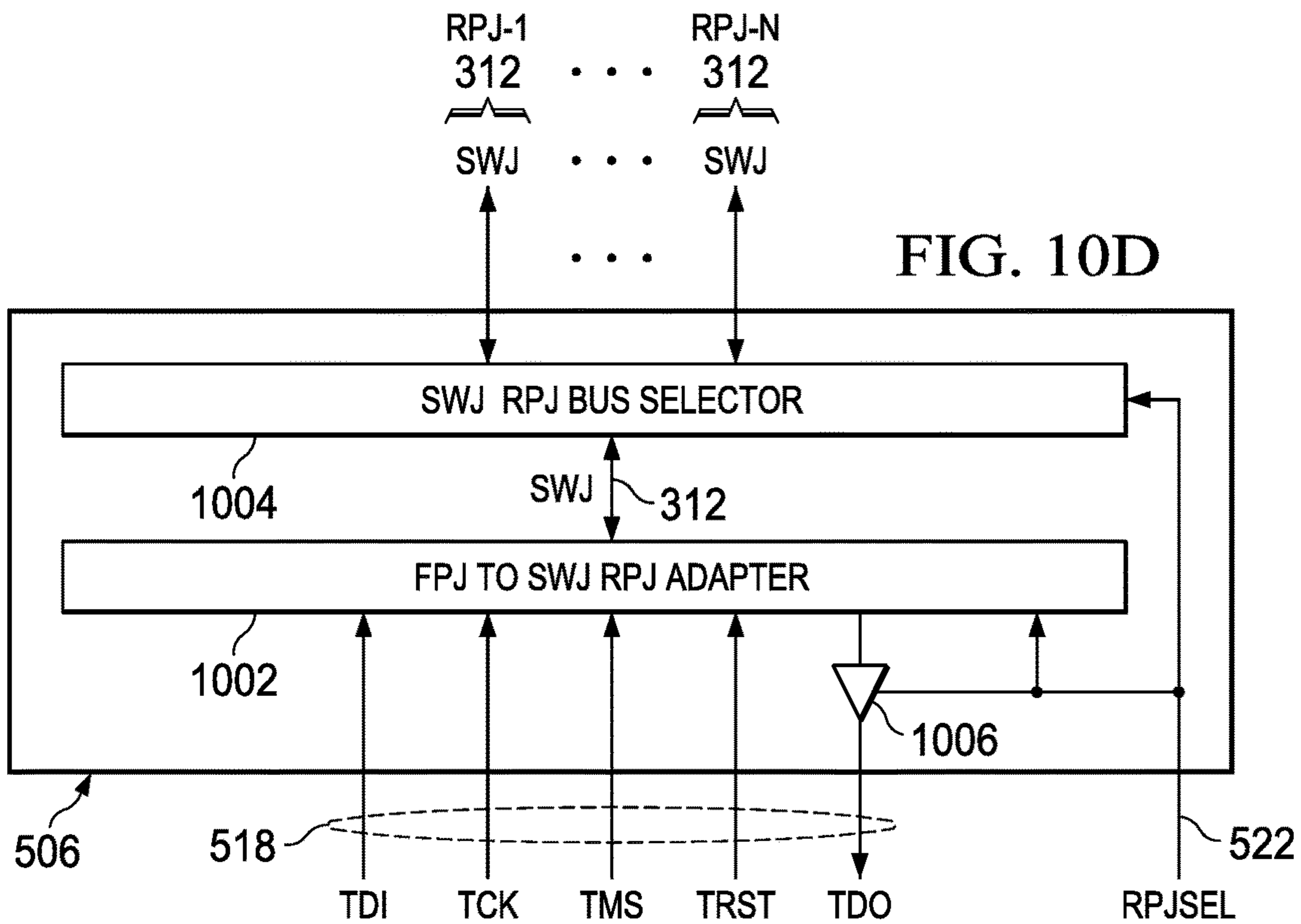
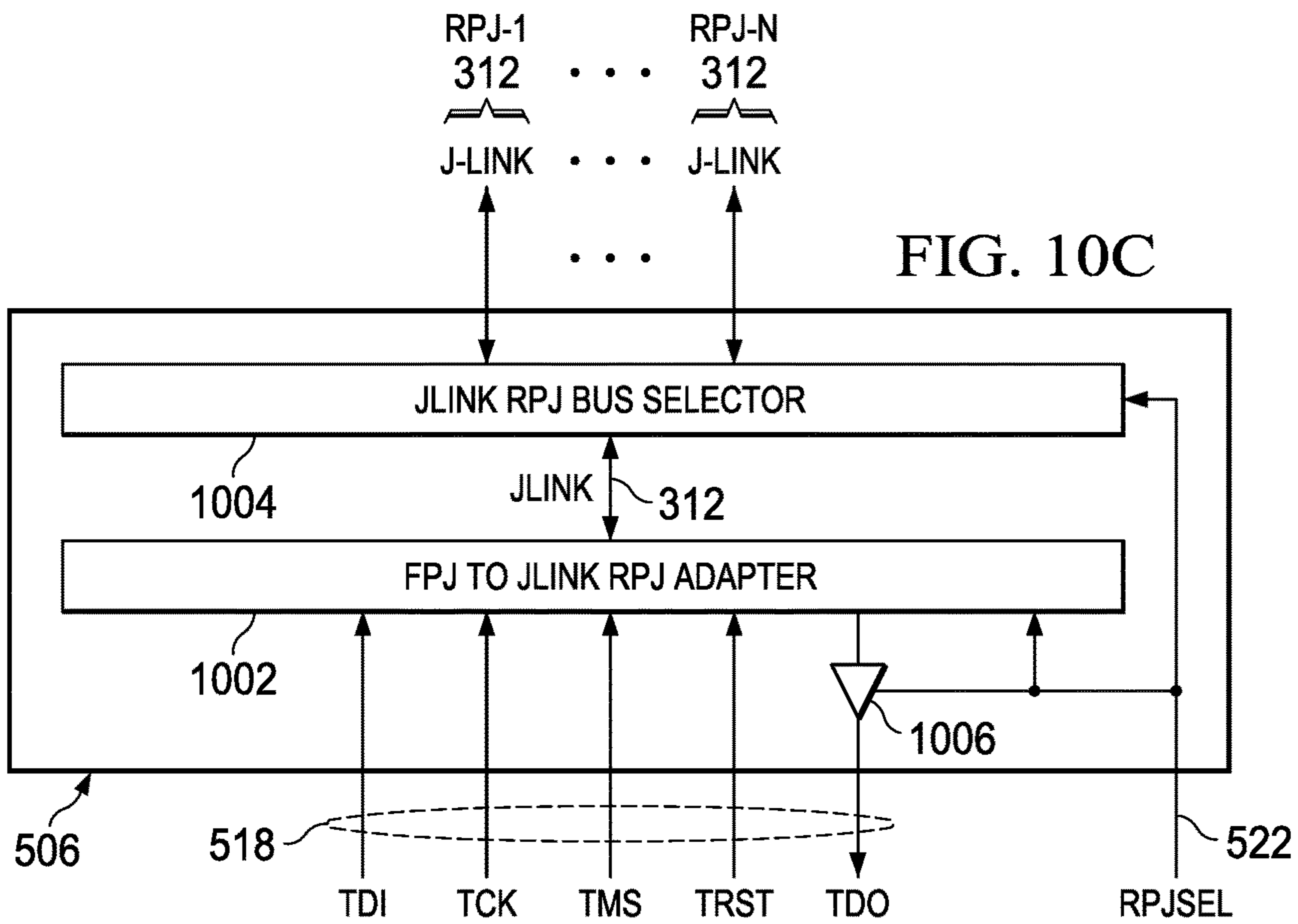
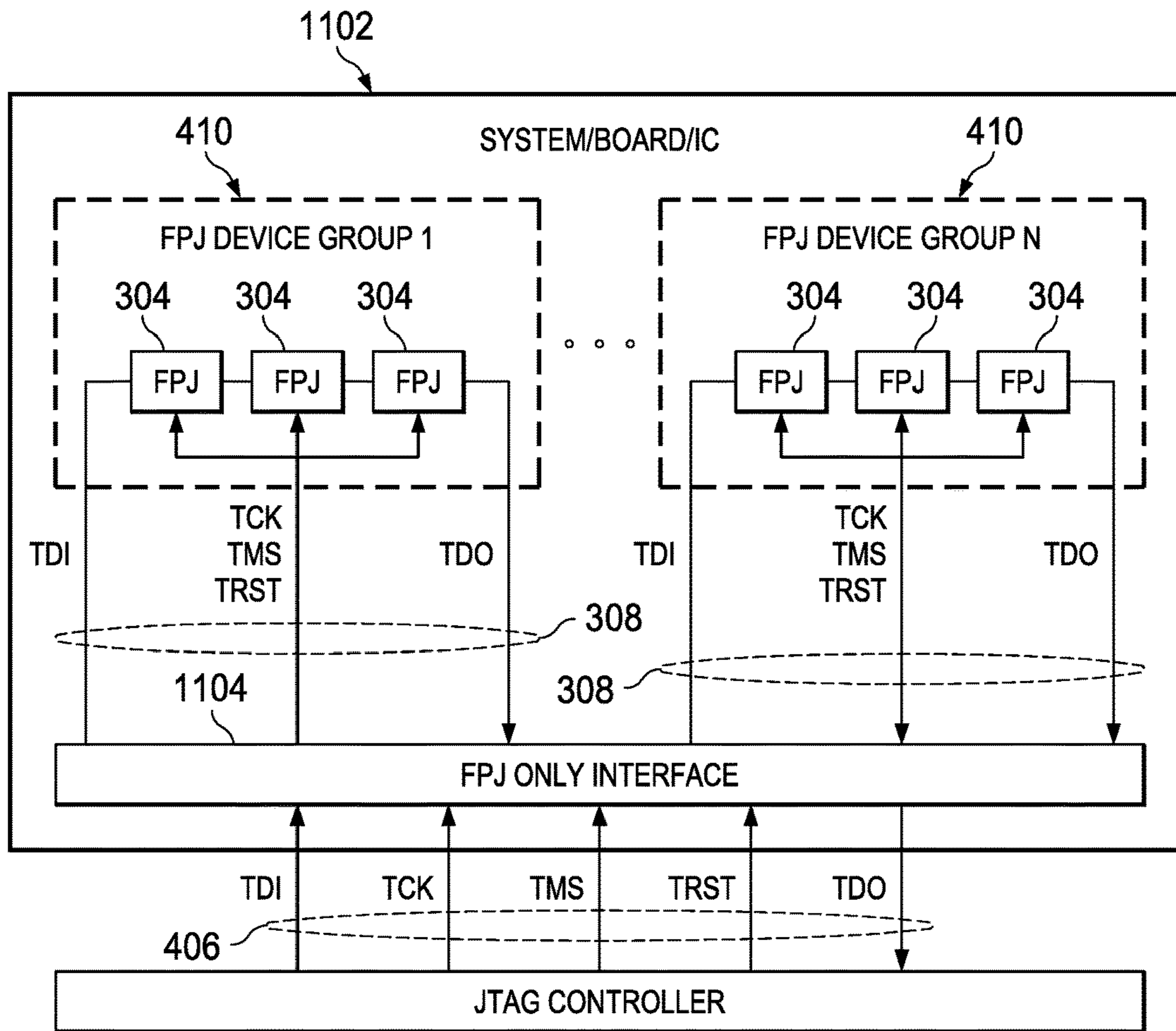


FIG. 10

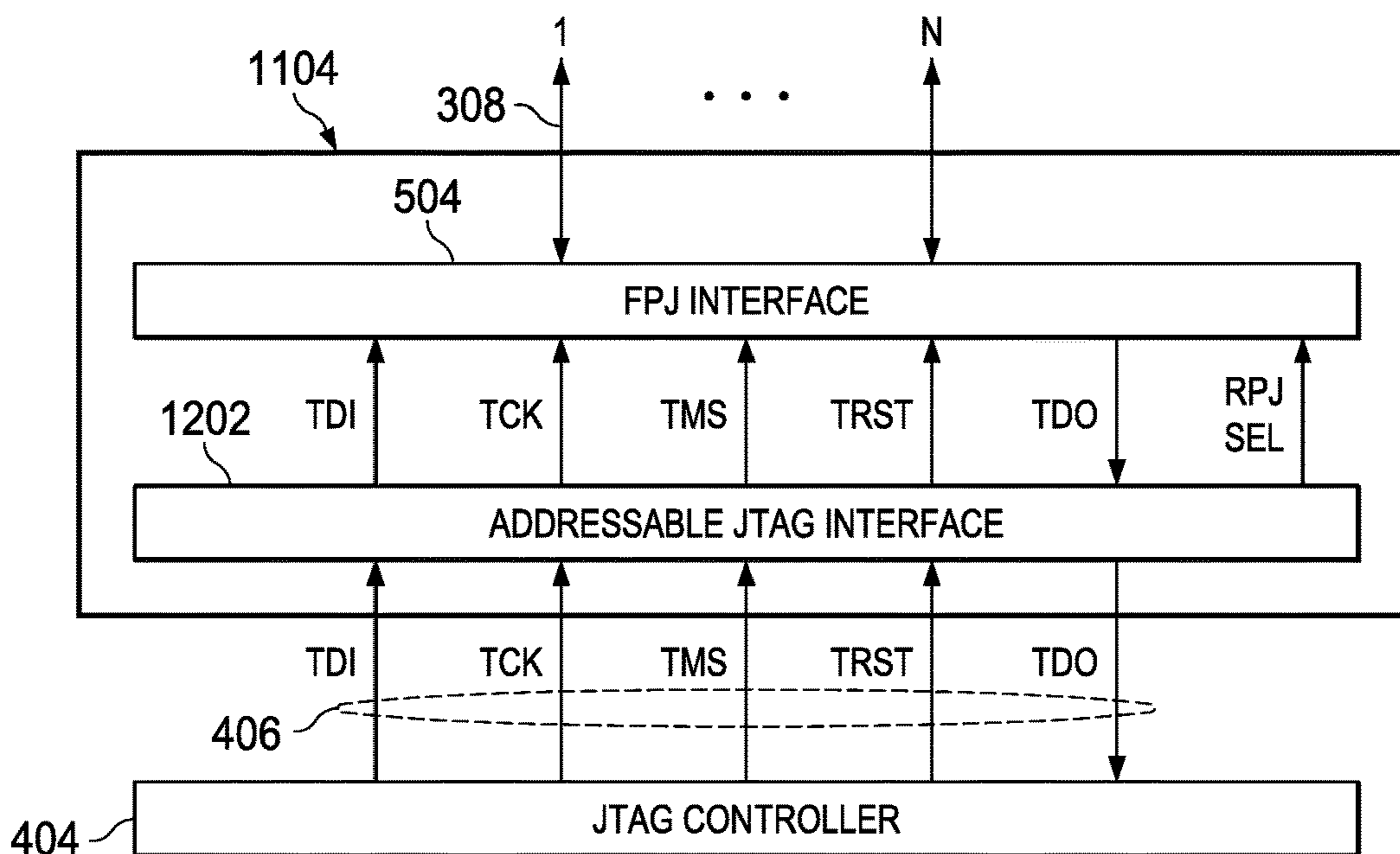






404

FIG. 11



404

FIG. 12

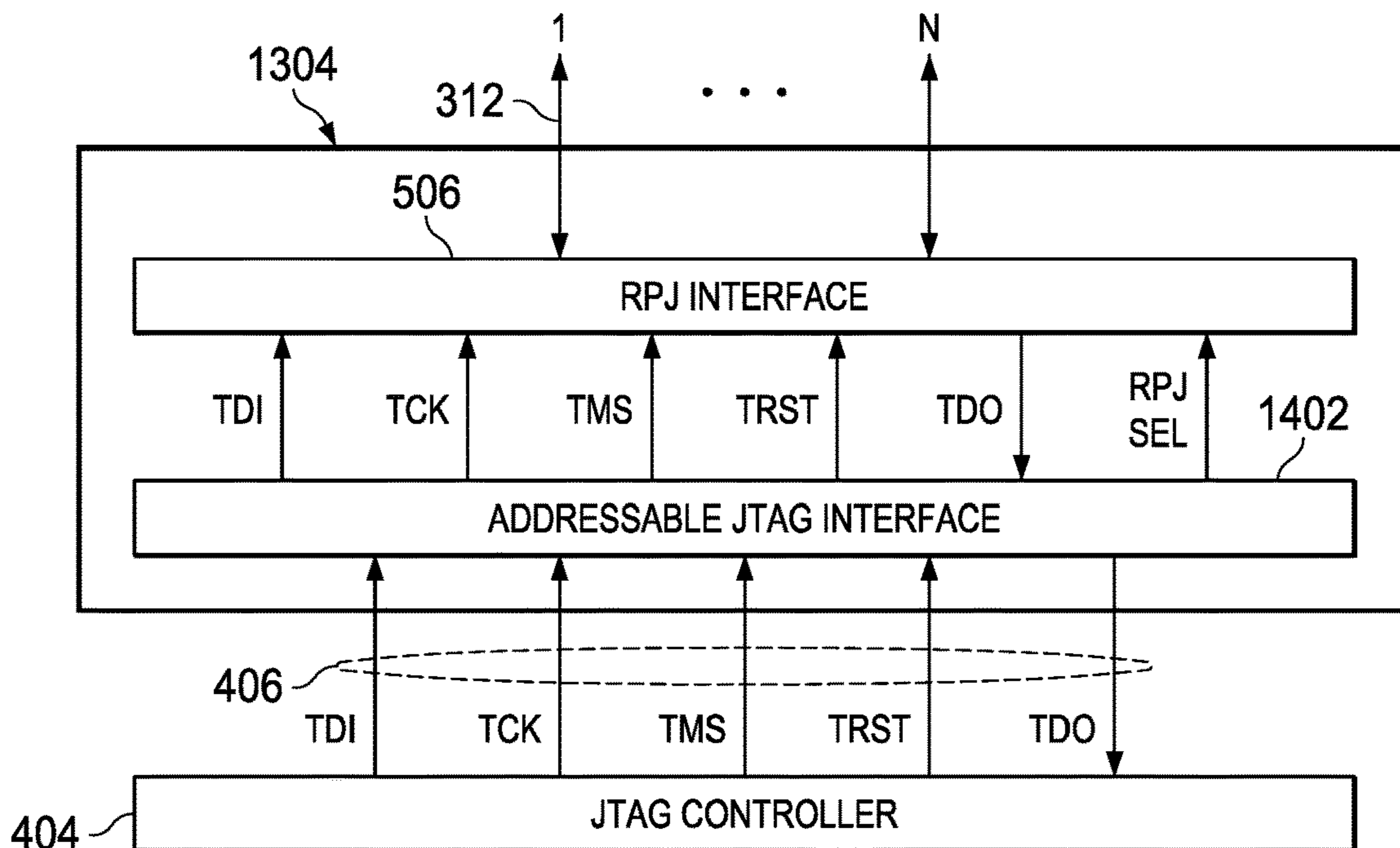
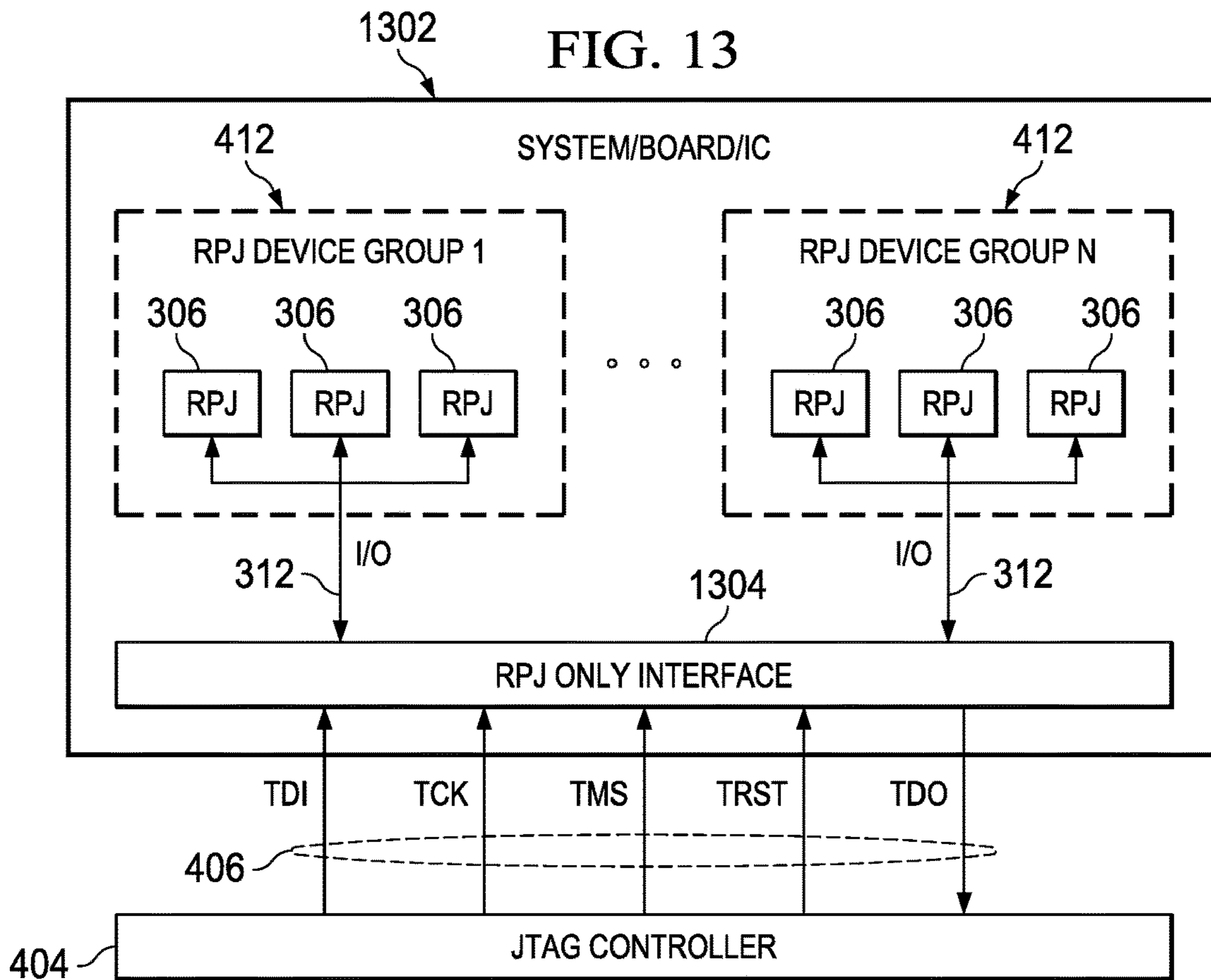


FIG. 14

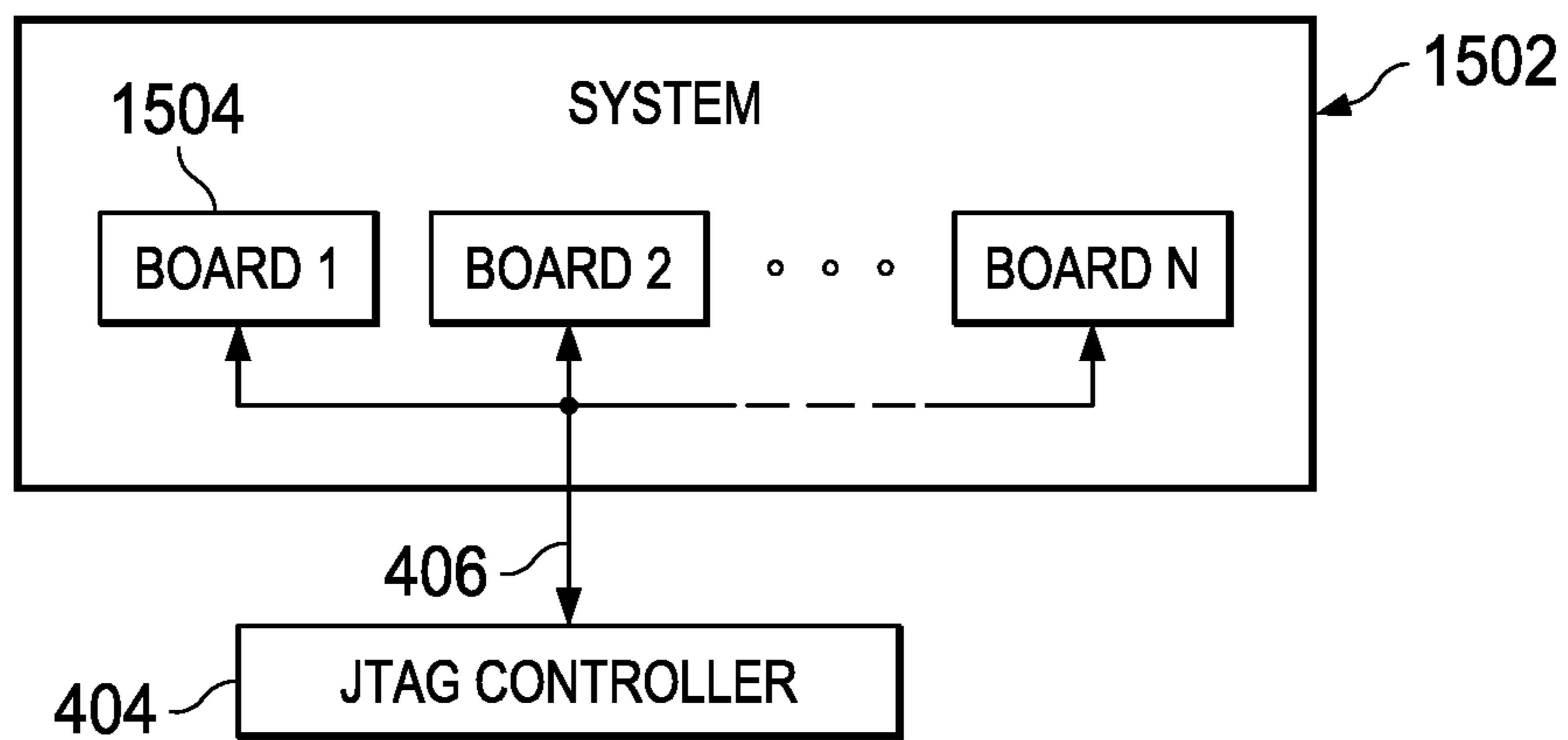


FIG. 15

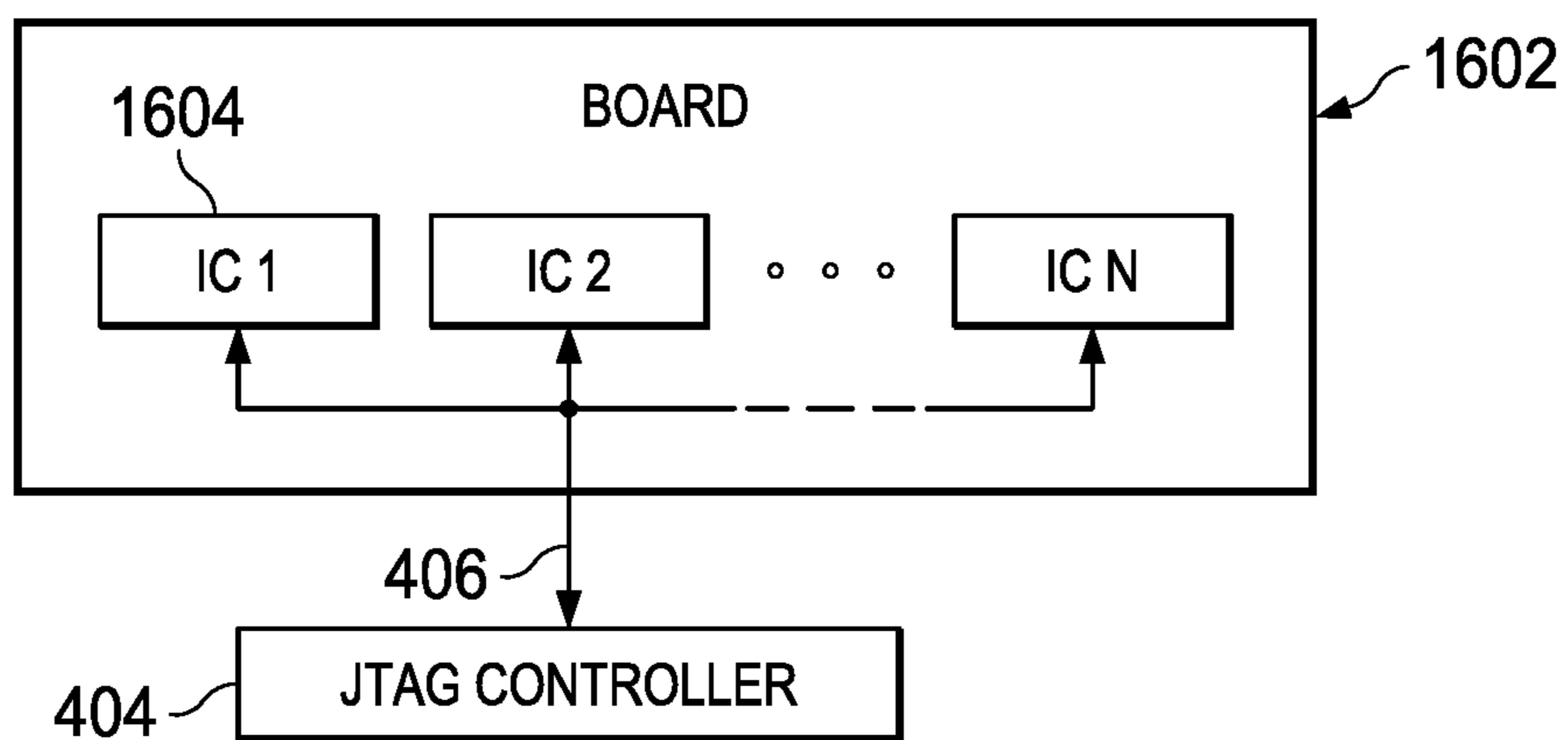


FIG. 16

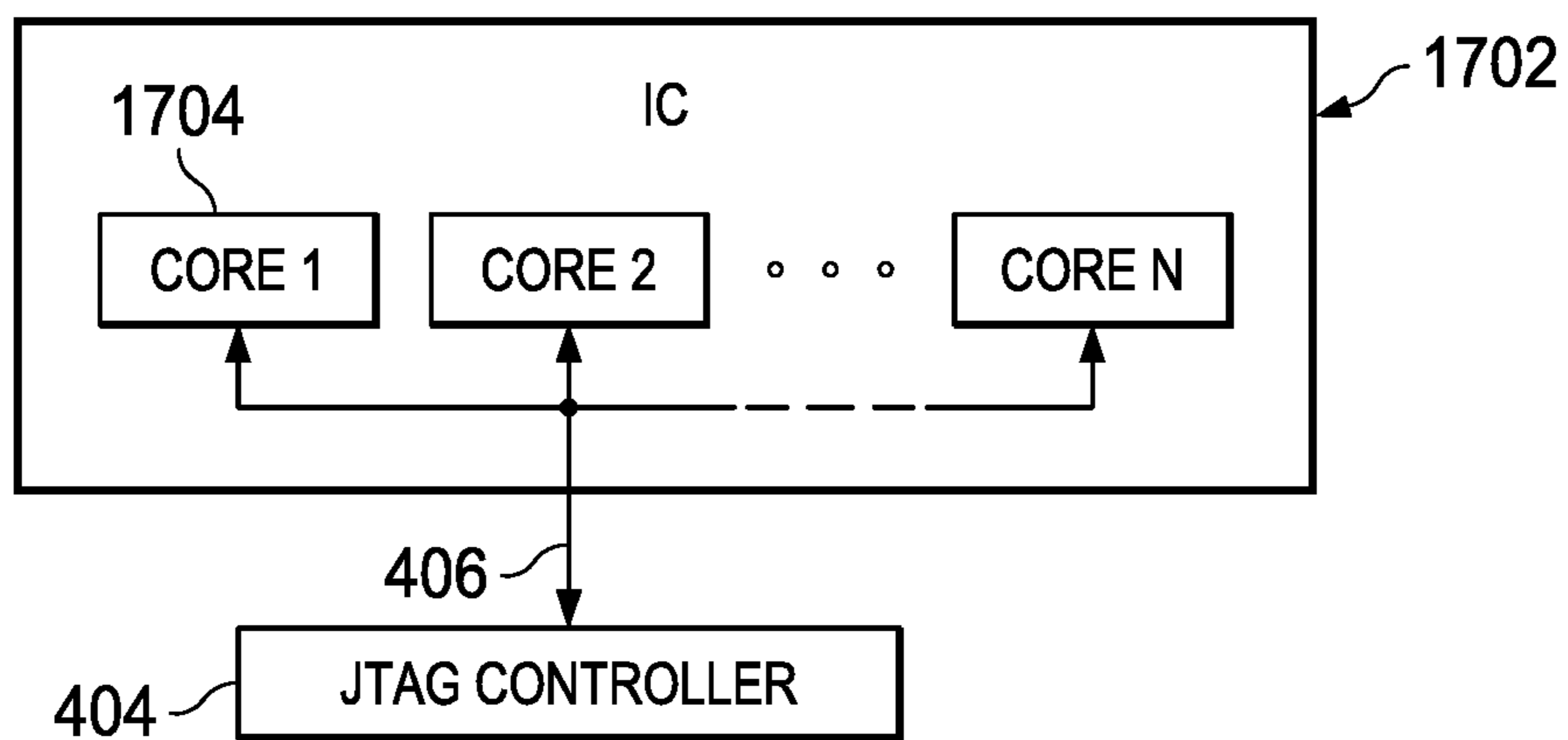


FIG. 17

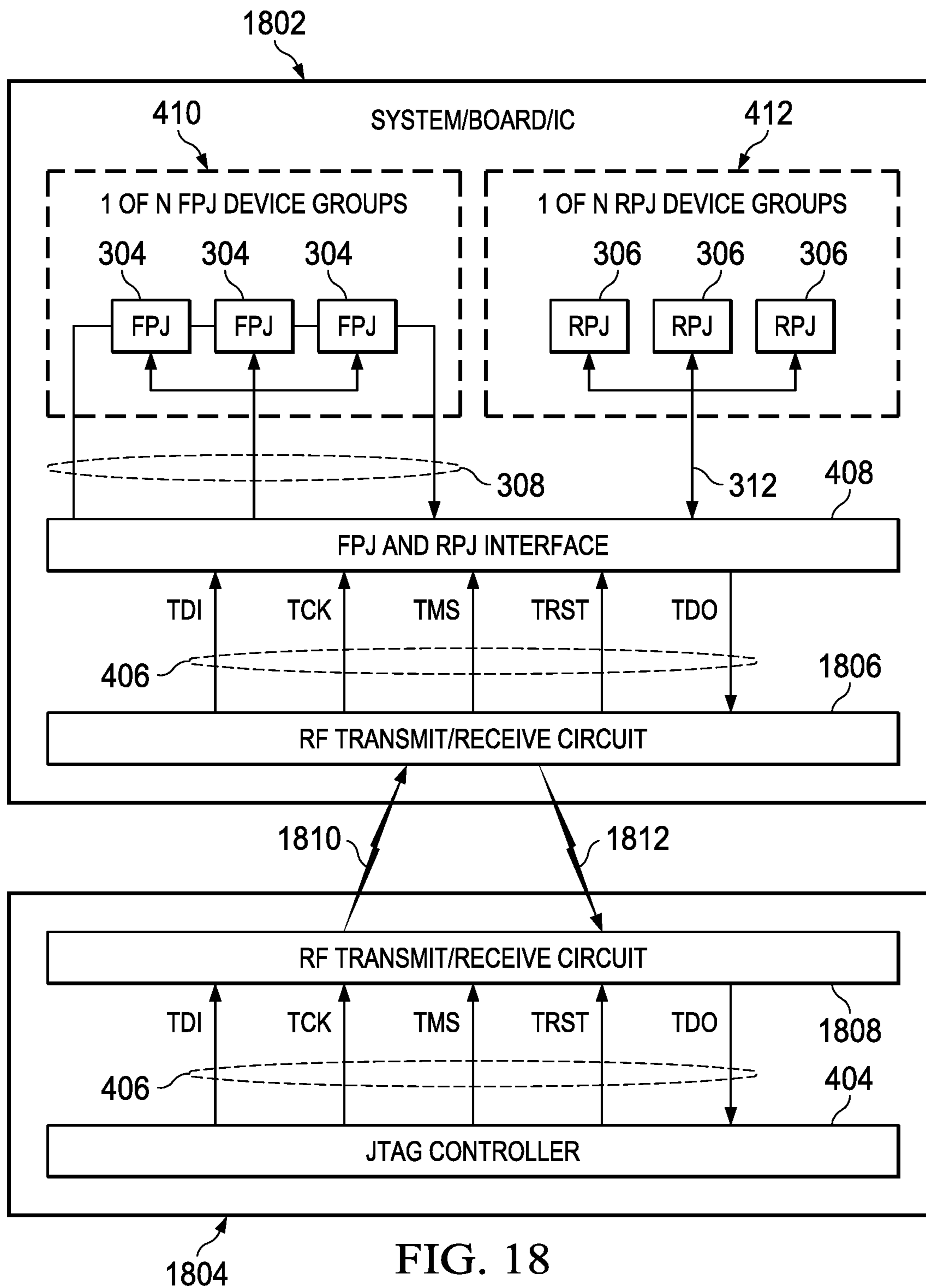


FIG. 18

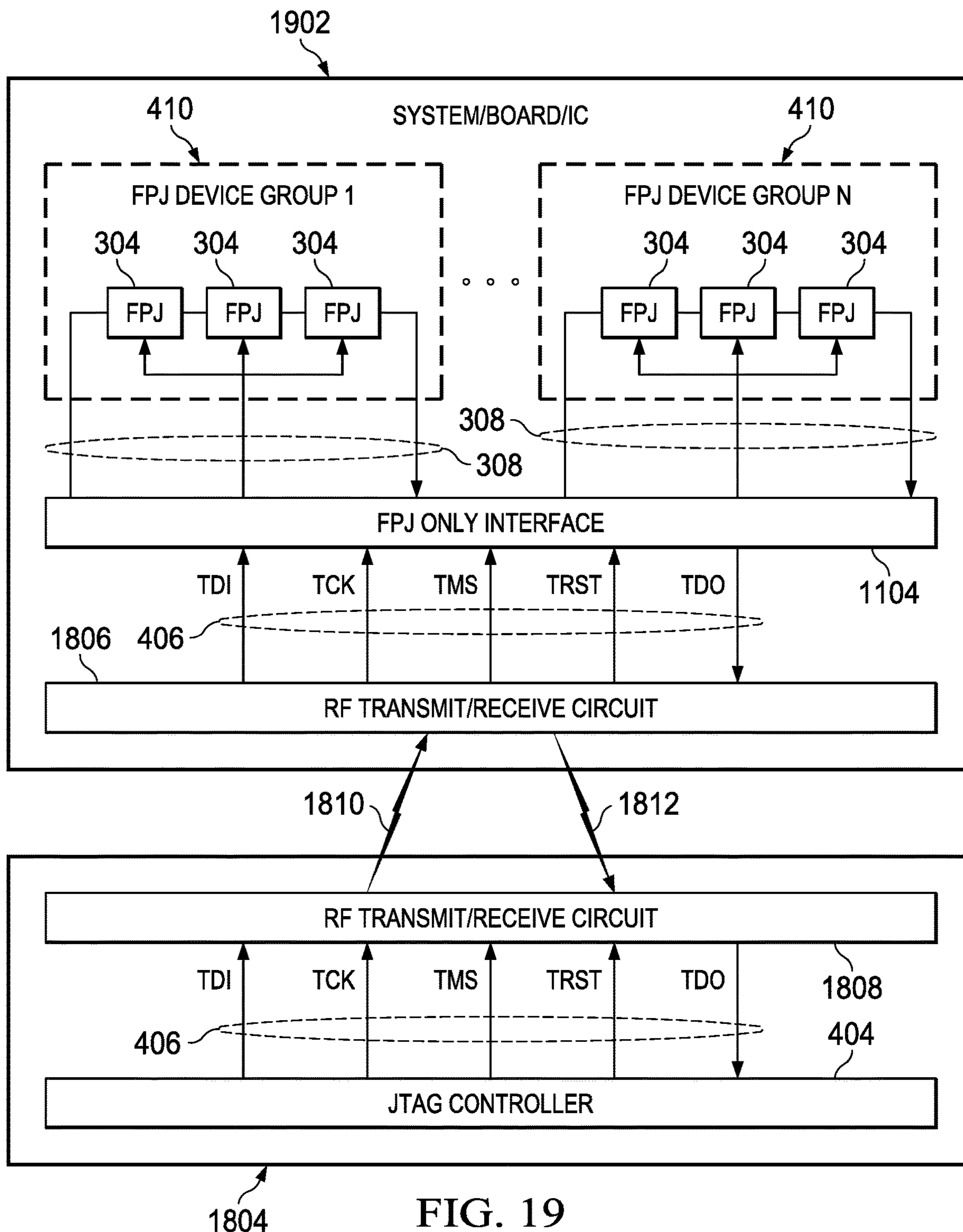


FIG. 19

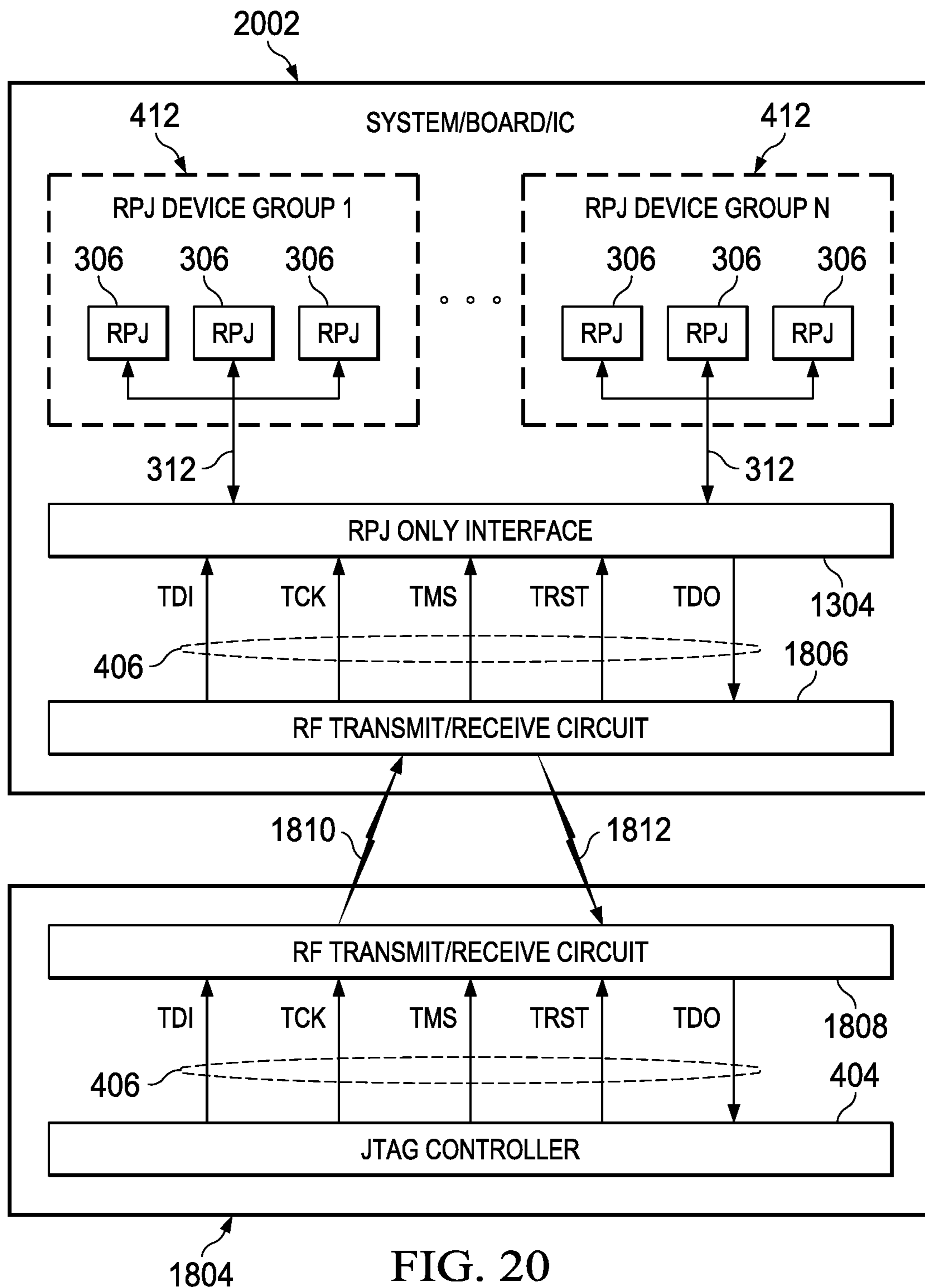


FIG. 20

SWITCHING FPI BETWEEN FPI AND RPI FROM RECEIVED BIT SEQUENCE

CROSS REFERENCE TO RELATED PATENTS

This application is a divisional of prior application Ser. No. 16/043,468, filed Jul. 24, 2018, now U.S. Pat. No. 10,459,028, issued Oct. 29., 2019;

Which was a divisional of prior application Ser. No. 15/467,485, filed Mar. 23, 2017, now U.S. Pat. No. 10,054,633, granted Aug. 21, 2018;

Which was a divisional of prior application Ser. No. 15/159,171, filed May 19, 2016, now U.S. Pat. No. 9,645,198, granted May 9, 2017;

Which was a divisional of prior application Ser. No. 14/815,396, filed Jul. 31, 2015, now U.S. Pat. No. 9,372,230, granted Jun. 21, 2016;

Which was a divisional of prior application Ser. No. 14/456,125, filed Aug. 11, 2014, now U.S. Pat. No. 9,128,152, granted Sep. 8, 2015;

Which was a divisional of prior application Ser. No. 13/488,956, filed Jun. 5, 2012, now U.S. Pat. No. 8,839,060, granted Sep. 16, 2014;

Which was a divisional of prior application Ser. No. 13/078,621, filed Apr. 1, 2011, now U.S. Pat. No. 8,225,157, granted Jul. 17, 2012;

Which was a divisional of prior application Ser. No. 12/883,629, filed Sep. 16, 2010, now U.S. Pat. No. 7,945,832, granted May 17, 2011;

which is a divisional of prior application Ser. No. 11/874,594, filed Oct. 18, 2007, now U.S. Pat. No. 7,818,641, granted Oct. 19, 2010;

which claims priority from Provisional Application No. 60/829,979, filed Oct. 18, 2006.

FIELD OF THE DISCLOSURE

This disclosure relates to an interface for accessing full and reduced pin JTAG devices on a substrate.

BACKGROUND OF THE DISCLOSURE

Electrical devices, which may be boards, ICs or embedded cores within ICs, require JTAG interfaces to provide testing and debugging of the device's hardware and software designs. In the past, device test and debug interfaces used the full pin JTAG interface consisting of TDI, TCK, TMS, TRST and TDO signal pins. The TRST pin is optional. More recently, reduced pin JTAG interfaces are being used for test and debug when device pins are not available for the full pin JTAG interface. Substrates, boards or ICs, containing both full and reduced pin JTAG devices will therefore require a full pin JTAG interface for accessing the full pin JTAG devices and a separate reduced pin JTAG interface for accessing the reduce pin JTAG devices. Requiring both a full and reduced pin JTAG interface on substrates complicates test and debug operations. Ideally, and according to the disclosure, substrate test and debug operations should be done without requiring the substrate to have both a full and reduced JTAG interface.

FIG. 1 illustrates an example of a full pin JTAG (FPJ) interface on a device. Full pin JTAG (IEEE 1149.1) interfaces comprising a TDI, TCK, TMS, TRST and TDO signals are well known and broadly used in the industry for testing, debugging, programming and/or other operations.

FIG. 2 illustrates an example of a reduced pin JTAG (RPJ) interface on a device. Reduced pin JTAG interfaces are

relatively new in the industry and typically comprised no more than one or two interface signals to carry out test, debug, programming and/or other operations.

FIG. 2A illustrates an addressable type of RPJ interface that requires a clock (CLK) and a data I/O (DIO) signal. This type of RPJ interface is described in detail in a 2006 IEEE International Test Conference paper by Whetsel titled "A High Speed Reduced Pin Count JTAG Interface", which is incorporated and referenced herein.

FIG. 2B illustrates another addressable type of RPJ interface that requires a clock (TCK) and a data I/O (TMSC) signal. This type of RPJ interface is the subject of developing IEEE standard P1149.7 and described in a 2006 white paper titled "MIPI Test and Debug Interface Framework", which is incorporated and referenced herein.

FIG. 2C illustrates a non-addressable type of RPJ interface that requires only a single I/O signal referred to as a JTAG Link (JLINK) signal. This JLINK interface was developed by DebugInnovation. The JLINK interface is described on DebugInnovation's website, which is incorporated and referenced herein.

FIG. 2D illustrates a non-addressable type of RPJ interface that requires only a single I/O signal referred to as a Single Wire JTAG (SWJ) signal. This SWJ interface was developed by ARM Ltd. The SWJ interface is described on ARM's website, which is incorporated and referenced herein.

While each of the addressable and non-addressable RPJ interfaces of FIG. 2A-2D are operationally different, they can all be used to achieve a RPJ interface for device test, debug, programming and other operations. Throughout the remainder of this description the term RPJ interface is general and can be used to reference any of the RPJ interfaces shown in FIGS. 2A-2D, as well as any other type of RPJ interface.

FIG. 3 illustrates a substrate 302, which can be a system, board or IC, that includes one or more FPJ (304) devices and one or more RPJ (306) devices. While plural FPJ devices 304 are shown in a daisy-chain, a single FPJ device may exist as well. Further, while plural addressable RPJ devices 306 are shown bussed together, a single non-addressable RPJ device 306 may exist as well. The devices 304-306 can be boards in a system, ICs on a board, or cores within an IC. As seen the FPJ devices 304 require a full pin JTAG interface 308 to a FPJ controller 310 and the RPJ devices 306 require a separate reduced pin interface 312 to a separate RPJ controller 314. Thus for test, debug, programming or other operations, the substrate 302 disadvantageously requires two separate JTAG interface 308 and 312 coupled to two separate JTAG controllers 310 and 314.

The disclosure, as will be described in detail below, does not require substrates 302 to have two separate JTAG interface 308 and 312 each coupled to two separate JTAG controllers 310 and 314. Advantageously therefore, the disclosure provides for substrate test, debug, programming and other operations to FPJ and RPJ devices to occur over a single interface coupled to a single JTAG controller. In the following description JTAG access FPJ or RPJ device interfaces includes access required for device testing, device debug, device programming, or any other operation performed using a FPJ or RPJ device interface.

BRIEF SUMMARY OF THE DISCLOSURE

The disclosure provides a process and apparatus for providing a single JTAG controller to access FPJ and RPJ

devices residing on a substrate using only a single interface between the JTAG controller and substrate.

BRIEF DESCRIPTION OF THE VIEWS OF THE DRAWINGS

FIG. 1 illustrates a full pin JTAG (FPJ) interface for accessing a device.

FIG. 2 illustrates a reduced pin JTAG (RPJ) interface for accessing a device.

FIG. 2A illustrates a device including a first known type of RPJ interface.

FIG. 2B illustrates a device including a second known type of RPJ interface.

FIG. 2C illustrates a device including a third known type of RPJ interface.

FIG. 2D illustrates a device including a fourth known type of RPJ interface.

FIG. 3 illustrates a substrate containing FPJ and RPJ devices interfaced to separate FPJ and RPJ controllers.

FIG. 4 illustrates a substrate containing FPJ and RPJ devices interfaced to a single JTAG controller via a FPJ & RPJ Interface according to the disclosure.

FIG. 5 illustrates the FPJ & RPJ Interface of FIG. 4.

FIG. 6 illustrates the addressable JTAG interface of FIG. 5.

FIG. 7 illustrates the shadow protocol circuit of FIG. 6.

FIG. 8A illustrates the state diagram of an IEEE 1149. TAP state machine.

FIG. 8B illustrates the state diagram of the shadow protocol detection circuit of FIG. 7.

FIG. 8C illustrates an example implementation of the shadow protocol detection circuit of FIG. 7.

FIG. 8D illustrates an example implementation of the address circuit of FIG. 7.

FIG. 8E illustrates an example implementation of the command circuit of FIG. 7.

FIG. 9 illustrates the FPJ interface of FIG. 5.

FIG. 10 illustrates the RPJ interface of FIG. 5.

FIG. 10A illustrates the RPJ interface of FIG. 10 designed to adapt an FPJ interface into a number of separate SBT Based RPJ interfaces.

FIG. 10B illustrates the RPJ interface of FIG. 10 designed to adapt an FPJ interface into a number of separate IEEE P1149.7 RPJ interfaces.

FIG. 10C illustrates the RPJ interface of FIG. 10 designed to adapt an FPJ interface into a number of separate JLINK RPJ interfaces.

FIG. 10D illustrates the RPJ interface of FIG. 10 designed to adapt an FPJ interface into a number of separate SWJ RPJ interfaces.

FIG. 11 illustrates a substrate containing only FPJ devices interfaced to a single JTAG controller via a FPJ Only Interface according to the disclosure.

FIG. 12 illustrates the FPJ Only Interface of FIG. 11.

FIG. 13 illustrates a substrate containing only RPJ devices interfaced to a single JTAG controller via a RPJ Only Interface according to the disclosure.

FIG. 14 illustrates the RPJ Only Interface of FIG. 13.

FIG. 15 illustrates a system (substrate) of boards (devices), each board comprising FPJ and/or RPJ ICs which are accessed via the architecture of the disclosure.

FIG. 16 illustrates a board (substrate) of ICs (devices), each IC comprising FPJ and/or RPJ cores which are accessed via the architecture of the disclosure

FIG. 17 illustrates an IC (substrate) of cores (devices), each core comprising FPJ and/or RPJ sub-cores which are accessed via the architecture of the disclosure.

FIG. 18 illustrates the FPJ & RPJ access architecture of the disclosure adapted to utilize wireless communication between the substrate (system/board/IC) and JTAG controller.

FIG. 19 illustrates the FPJ Only access architecture of the disclosure adapted to utilize wireless communication between the substrate (system/board/IC) and JTAG controller.

FIG. 20 illustrates the RPJ Only access architecture of the disclosure adapted to utilize wireless communication between the substrate (system/board/IC) and JTAG controller.

DETAILED DESCRIPTION OF THE DISCLOSURE

FIG. 4 illustrates a substrate **402** that includes the FPJ and RPJ device access architecture of the disclosure. As seen, the architecture includes an FPJ & RPJ Interface circuit **408** that is coupled to; (1) a group **410** of FPJ devices **304** via FPJ interface **308**, (2) a group **412** of RPJ devices **306** via RPJ interface **312**, and (3) a JTAG controller **404** via a JTAG interface bus **406**. Any number of groups **410** of one or more FPJ devices **304** may be coupled to JTAG controller **404** by separate FPJ interfaces **308**. Any number of groups **412** of one or more RPJ devices **306** may be coupled to JTAG controller **404** by separate RPJ interfaces **312**. The JTAG controller **404** may access a group of one or more FPJ devices or a group of one or more RPJ devices by the FPJ & RPJ interface circuit **408** via JTAG interface bus **406**.

FIG. 5 illustrates in more detail the FPJ & RPJ Interface circuit **408** of FIG. 4. As seen, circuit **408** comprises an addressable JTAG interface **502**, a FPJ interface **504**, and a RPJ interface **506**. The JTAG interface **502** is coupled to a JTAG controller **404** via bus **406** which includes a TDI **508**, TCK **510**, TMS **512**, TRST **514**, and TDO **516** signal. The TDI **508** signal provides data input from the JTAG controller **404**. The TCK **510** signal provides clock input from the JTAG controller **404**. The TMS **512** signal provides control input from the JTAG controller **404**. The TRST **514** signal provides reset input from the JTAG controller **404**. The TDO **516** signal provides data output to the JTAG controller **404**. The JTAG interface **502** is coupled to the FPJ interface **504** via busses **518** and **520** and to RPJ interface **506** via busses **518** and **522**. The FPJ interface **504** interfaces to one or more (N) FPJ device groups **410** via FPJ busses **308**. The RPJ interface **506** interfaces to one or more (N) RPJ device groups **412** via RPJ busses **312**.

FIG. 6 illustrates the addressable JTAG interface **502** in more detail, which comprises a shadow protocol circuit **602**, And gate **604**, and 3-state buffer **606**. Addressable JTAG Circuit **602** inputs the TDI, TCK, TMS and TRST signals from bus **406** and outputs a select FPJ (SELPJ) bus **520** to FPJ interface **504**, a select RPJ (SELRPJ) bus **522** to RPJ interface **506**, and an enable (ENA) signal **608** to And gate **604** and 3-state buffer **606**. The SELFPJ bus **520** is used to select an FPJ device group **410** for access, the SELRPJ bus **522** is used to select an RPJ device group **412** for access, and the ENA signal **608** enables And gate **604** and 3-state buffer **606**, to provide for bus **406** to be fully coupled to bus **518**. When bus **406** is fully coupled to bus **518**, the selected FPJ **410** or RPJ **412** device group may be accessed by the JTAG controller **404** via bus **406**.

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FIG. 7 illustrates the shadow protocol circuit 602 in more detail, which comprises a shadow protocol detection circuit 702, command circuit 704, and address circuit 706. The shadow protocol detection circuit 602 inputs the TDI, TCK, TMS and TRST signals from bus 406 and a match signal from address circuit 706. The detection circuit 702 outputs a command input (CI) signal and command control signals (CC) to command circuit 704 and an address input (AI) signal and address control signals (AC) to address circuit 706. The command circuit 704 outputs the FPJSEL bus 520 to FPJ interface 504 and the RPJSEL bus 522 to RPJ interface 522.

When the JTAG controller 404 is in the RunTest/Idle state 802, the Pause-DR state 804, or the Pause-IR state 806 of the IEEE 1149.1 TAP state diagram 801 of FIG. 8A, the Detection circuit 702 is enabled to respond to a shadow protocol message 707 input on TDI to input address data to the address circuit 704 and command data to the command circuit 706. If the JTAG controller 404 is not in one of these states 802-806, the detection circuit 702 is disabled from responding to the message 707. The detection circuit and all FPJ and RPJ devices coupled to the FJP & RPJ interface 408 are reset by the TRST signal going low or by the JTAG bus 406 transitioning to the Test Logic Reset state of FIG. 8A.

The shadow protocol message 707 consists of a start field 708 comprising an idle symbol (I) 718 and a select symbol (S) 720, an address field 710 comprising a number of logic one or zero address symbols (A) 722 and 724, a delimiter field 712 comprising a select symbol (S) 720, a command field 714 comprising a number of logic one or zero command symbols (C) 722 and 724, and a stop field 716 comprising a select symbol (C) 720 and an idle symbol (I) 718. The symbols 718-724 are each defined by a pair of logic bits, with the I symbol 718 being two logic ones, the S symbol 720 being two logic zeros, the logic zero A or C symbol 722 being a logic one followed by a logic zero, and the logic one A or C symbol 724 being a logic zero followed by a logic one. As seen, the TCK times the symbol bit pair inputs on TDI. If desired the symbol bit pair definitions may be defined differently from that shown in examples 718-724.

FIG. 8B illustrates the state diagram 807 of the detection circuit 702. If the JTAG bus 406 is not in TAP states 802, 804, or 806, the detection circuit 702 will be in the idle state 808. If the JTAG bus 406 is in state 802, 804 or 806, the detection circuit 702 transitions to state 810 to enable the detection of a shadow protocol message 707. If a message start field 708 occurs in state 810 the detection circuit 702 transitions to state 812 to input an address field 710 to the address circuit 704. When the delimiter field 712 occurs at the end of an address field input, the detection circuit transitions to state 814 to evaluate the match signal output from address circuit 706 to determine if the address input to the address circuit 704 matches the address of the FPJ & RPJ interface 408. If it does not match, the detection circuit transitions to and remains in state 810 for the remainder of the message 707. If it does match, the detection circuit transitions to state 816 to enable the command circuit 706 for receiving a command field 714. When the stop field 716 occurs at the end of the command field 714 input, the detection circuit transitions to state 818 to output the command data on the FPJSEL 520 and RPJSEL 522 busses to select an FPJ device group 410 or an RPJ device group 412 for access and to output the ENA signal 608 to fully couple busses 406 and 518. From state 818, the detection circuit 702 transitions to state 810. When the JTAG bus 406 transitions out of state 802, 804 or 806 to resume JTAG operations, the detection circuit 702 returns to the idle state 808.

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Following the above described shadow protocol message input 707, the selected FPJ 520 or RPJ 522 device group can be accessed by transitioning through the states of the IEEE 1149.1 TAP state diagram 801. When access to another FPJ 520 or RPJ 522 device group is desired, the above described process is repeated.

FIG. 8C illustrates an example implementation 820 of the shadow protocol detection circuit 702, which consists of a state machine 822 and a TAP state monitor 824. The TAP state monitor is basically an IEEE 1149.1 TAP that is used to track the state of the JTAG bus 406. The TAP state monitor 824 outputs a RST signal 827 and an Enable signal 826 to the state machine 822. The TAP state monitor 824 outputs a low on RST 827 whenever the JTAG bus 406 transitions to the Test Logic Reset state of FIG. 8A. The TAP state monitor 824 outputs a high on the Enable signal 826 to state machine 822 whenever the JTAG bus 406 is in the RunTest/Idle state, the Pause-DR state, or the Pause-IR state. If the Enable signal 826 is low the JTAG bus 406 is not in one of these states and the state machine 822 will be forced to the idle state 808 of FIG. 8B. If the enable signal 826 is high the JTAG bus 406 is in one of these states and the state machine 822 will transition to state 810 of FIG. 8B to look for the start field 708 of a message 707.

When a message is started, state machine 822 will transition to state 812 of FIG. 8B to decode the address symbols (A) input from TDI during address input field 710 into logic one or zero bits and output these bits on AI to the address circuit 706. The state machine outputs address control (AC) to the address circuit 706 to cause the AI bits to be input to the address circuit 706. In response to detecting the delimiter field 712 the state machine 822 will transition to state 814 to interpret the Match signal from address circuit 706 as previously described. If an address match is detected, the state machine transitions to state 816 to decode the command symbols (C) input from TDI during command input field 714 into logic one or zero bits and output these bits on CI to the command circuit 704. If an address match does not occur, state machine 822 transitions to state 810 of FIG. 8B. A transition from state 814 to state 810, as a result of an address mismatch, sets the ENA signal 608 output from state machine 822 low to disable And gate 604 and TDO 3-state buffer 606, which fully decouples bus 406 from bus 518 of FIG. 6.

During command bit outputs to command circuit 704, the state machine 822 outputs command control (CC) to the command circuit 704 to cause the command bits to be input to the command circuit 704. In response to the stop field 716, the state machine 822 stops command bit inputs to command circuit 704, transitions to state 818 of FIG. 8B to output control on CC to cause the command (FPJSEL bus 520 and RPJSEL bus 522) to be output from the command circuit 704. Also in state 818, the state machine 822 sets the ENA signal 608 high to enable And gate 604 and TDO 3-state buffer 606 of FIG. 6 to fully couple busses 406 and 518.

In response to a low on TRST of JTAG bus 406, the state machine 822, TAP state monitor 824, address circuit 706, and command circuit 704 are reset. Also in response to the RST input 827 from TAP state monitor 824 the state machine 822, address circuit 706, and command circuit 704 are reset.

FIG. 8D illustrates an example implementation 828 of the address circuit 706, which comprises a shift register 830, update register 832, comparator 834, and device address 836. The shift register 830 receives the address bit input (AI) and an A-Clock input from state machine 822. The A-clock input is a signal on the AC bus and is used to clock in the

address bits from the AI input during state **812** of FIG. **8B**. The update register **832** inputs the parallel address output from shift register **830** in response to an A-Update signal from the AC bus. The update register **832** outputs the updated address to comparator **834** during state **814** of FIG. **8B**. The comparator compares the address output from the update register to the device address **836**. If the addresses match, the Match signal from the comparator is set high. If the addresses do not match, the Match signal from the comparator is set low.

In response to a reset output from state machine **822** on the AC bus, as a result of the state machine receiving a low on the TRST or RST input, the update register **832** is reset to an address value that will not match the device address **836**.

FIG. **8E** illustrates an example implementation **838** of the command circuit **704**, which comprises a shift register **840** and an update register **842**. The shift register **840** receives the command bit inputs (CI) and a C-Clock input from state machine **822**. The C-clock input is a signal on the CC bus and is used to clock in the command bits from the CI input during state **816** of FIG. **8B**. The update register **842** inputs the parallel command output from shift register **840** in response to a C-Update signal from the CC bus during state **818** of FIG. **8B**. The update register **842** outputs the updated command to the FPJSEL bus **520** and RPJSEL bus **522**.

In response to a reset output from state machine **822** on the CC bus, as a result of the state machine receiving a low on the TRST or RST input, the update register **842** is reset to a value where the FPJSEL bus **520** does not select an FPJ device group and the RPJSEL bus **522** does not select a RPJ device group. Also in response to a TRST or RST input, the state machine sets the ENA signal **608** low to decouple busses **406** and **518** of FIG. **6**.

FIG. **9** illustrates the FPJ interface **504** of FIG. **5** in more detail. The FPJ interface comprises an FPJ bus linking circuit **902** and a TDO 3-state buffer **904**. The linking circuit **902** is coupled to the JTAG bus **518** and the FPJSEL bus **520** from the addressable JTAG interface circuit **502** and to FPJ device groups **410** via one or more JTAG busses **308**. The control input of the TDO 3-state buffer **904** is coupled to a signal from the FPJSEL bus **520**.

In response to an FPJ selection input on FPJSEL bus **520**, and when only one FPJ device group **410** is being accessed, the linking circuit **902** couples bus **518** to a selected bus **308** such that; TDI of bus **518** drives TDI of selected bus **308**, TCK of bus **518** drives TCK of selected bus **308**, TMS of bus **518** drives TMS of selected bus **308**, and TDO of selected bus **308** drives TDO of bus **518**, via the TDO 3-state buffer **904**.

In response to an FPJ selection input on FPJSEL bus **520**, and when a first and a second FPJ device group **410** are being accessed in a daisy-chain, the linking circuit **902** couples bus **518** to the selected first and second FPJ device groups **410**, via their busses **308**, such that; TDI of bus **518** drives TDI of the first selected bus **308**, TCK of bus **518** drives TCK of both first and second selected busses **308**, TMS of bus **518** drives TMS of both first and second selected busses **308**, TDO of the first selected bus **308** drives TDI of the second selected bus **308**, and TDO of the second selected bus **308** drives TDO of bus **518**, via the TDO 3-state buffer **904**.

The daisy-chaining of more than two FPJ device groups **410** is achieved by simply inputting control on FPJSEL bus **520** to select more than two FPJ device groups **410**, which couples TCK and TMS of bus **518** to all the selected FPJ device groups **410** via their busses **308**, daisy-chains the TDI

of bus **518** to the TDI of the first FPJ device group **410** via its bus **308**, forms TDO to TDI couplings between each intermediate FPJ device group **410** via their busses **308**, and finally coupling the TDO of the last selected FPG device group **410** to the TDO of bus **518** via TDO 3-state buffer **904**.

FIG. **10** illustrates the RPJ interface **506** of FIG. **5** in more detail. The RPJ interface comprises a FPJ to RPJ adapter circuit **1002**, a RPJ bus selector circuit **1004**, and a TDO 3-state buffer **1006**. The adapter circuit **1002** is coupled to the JTAG bus **518** and the RPJSEL bus **522** from the addressable JTAG interface circuit **502** and to the RPJ bus selector circuit **1004** via an RPJ I/O bus **312**. The RPJ bus selector **1004** is coupled to the RPJSEL bus **522** and to one or more RPJ HO busses **312**. The control input of the TDO 3-state buffer **1006** is coupled to a signal from the RPJSEL bus **522**.

In response to an RPJ selection input on RPJSEL bus **522** the adapter circuit **1002** and buffer **1006** are enabled and the bus selector circuit **1004** couples the I/O bus **312** from adapter circuit **1002** to a selected I/O bus **312** coupled to a RPJ device group **412**. Non-selected I/O busses **312** from selector circuit **1004** are not coupled to I/O bus **312** from adapter circuit **1002**. Following the RPJ selection input on RPJSEL bus **522**, the selected RPJ device group **412** may be accessed by the JTAG bus **518** via the adapter circuit **1002** and selector circuit **1004**. During the access, the adapter circuit **1002** operates to convert the JTAG protocol on bus **518** into an RPJ protocol such that RPJ interface **506** can communicate with the selected RPJ device group **412** via selector circuit **1004**.

FIG. **10A** illustrates an example RPJ interface **506** for communicating with the previously mentioned SBT based RPJ devices of FIG. **2A**. In this example the adapter circuit **1002** is designed to convert the JTAG protocol on bus **518** into the two signal (CLK & DIO) SBT based protocol on bus **312** for communicating with a selected SBT based RPJ device group **412** via selector **1004**. An example SBT based adapter **1002** is described in the referenced Whetsel paper. In this example, the SBT based RPJ bus selector **1004** is designed to couple the selected SBT based bus **312** of an SBT based device group **412** to the SBT based bus **312** from adapter **1002**.

FIG. **10B** illustrates an example RPJ interface **506** for communicating with the previously mentioned IEEE P1149.7 RPJ devices of FIG. **2B**. In this example the adapter circuit **1002** is designed to convert the JTAG protocol on bus **518** into the two signal (TCK & TMS) P1149.7 protocol on bus **312** for communicating with a selected P1149.7 RPJ device group **412** via selector **1004**. An example P1149.7 adapter **1002** is described in the referenced P1149.7 white paper. In this example, the P1149.7 RPJ bus selector **1004** is designed to couple the selected P1149.7 bus **312** of a P1149.7 device group **412** to the P1149.7 bus **312** from adapter **1002**.

FIG. **10C** illustrates an example RPJ interface **506** for communicating with the previously mentioned JLINK RPJ devices of FIG. **2C**. In this example the adapter circuit **1002** is designed to convert the JTAG protocol on bus **518** into the single signal JLINK protocol on bus **312** for communicating with a selected JLINK RPJ device **412** via selector **1004**. An example JLINK adapter **1002** is described on the referenced JLINK website. In this example, the JLINK RPJ bus selector **1004** is designed to couple the selected JLINK bus **312** of a JLINK device **412** to the JLINK bus **312** from adapter **1002**.

FIG. **10D** illustrates an example RPJ interface **506** for communicating with the previously mentioned SWJ RPJ

devices of FIG. 2D. In this example the adapter circuit **1002** is designed to convert the JTAG protocol on bus **518** into the single signal SWJ protocol on bus **312** for communicating with a selected SWJ RPJ device **412** via selector **1004**. An example SWJ adapter **1002** is described on the referenced ARM website. In this example, the SWJ RPJ bus selector **1004** is designed to couple the selected SWJ bus **312** of a SWJ device **412** to the SWJ bus **312** from adapter **1002**.

While FIGS. 10A-10D have shown how the RPJ interface **506** can communicate with four known types of RPJ device interfaces, it is not limited to communicating with only these four RPJ device interfaces. In general, the adapter **1002** and selector **1004** of the RPJ interface **506** can be designed to interface to any type of RPJ device interfaces.

FIG. 11 illustrates the JTAG access architecture **1102** of the disclosure adapted for only selecting FPJ device groups **410**. As seen, the only difference between the architecture of FIG. 11 and FIG. 4 is that the FJP & RPJ Interface circuit **408** of FIG. 4 has been replaced with an FPJ Only Interface circuit **1104** in FIG. 11.

FIG. 12 illustrates in more detail the FPJ Only Interface **1104** of FIG. 11. As seen, the FPJ Only Interface **1104** comprises the previously described FPJ Interface **504** and a modified addressable JTAG interface **1202**. The addressable JTAG interface **1202** is identical to the addressable JTAG interface **502** with the exception that the SELRPJ bus **522** and associated circuitry has been removed from shadow protocol circuit **602** of FIG. 6, the command circuit **704** of FIG. 7, and update register **842** of FIG. 8e. The procedure of selecting an FPJ device group **410** for access is the same as previously described.

FIG. 13 illustrates the JTAG access architecture **1302** of the disclosure adapted for only selecting RPJ device groups **412**. As seen, the only difference between the architecture of FIG. 13 and FIG. 4 is that the FJP & RPJ Interface circuit **408** of FIG. 4 has been replaced with an RPJ Only Interface circuit **1304** in FIG. 13.

FIG. 14 illustrates in more detail the RPJ Only Interface **1304** of FIG. 13. As seen, the RPJ Only Interface **1304** comprises the previously described RPJ Interface **506** and a modified addressable JTAG interface **1402**. The addressable JTAG interface **1402** is identical to the addressable JTAG interface **502** with the exception that the SELFPJ bus **520** and associated circuitry has been removed from shadow protocol circuit **602** of FIG. 6, the command circuit **704** of FIG. 7, and update register **842** of FIG. 8e. The procedure of selecting a RPJ device group **412** for access is the same as previously described.

FIG. 15 is provided to illustrate a system **1502** comprising multiple boards **1504**, each board **1504** including either the FPJ and RPJ device access architecture of FIG. 4, the FPJ Only device access architecture of FIG. 11, or the RPJ Only device access architecture of FIG. 13 to provide for a JTAG controller **404** to access FPJ and/or RPJ interfaces of ICs on the board **1104** via bus **406**.

FIG. 16 is provided to illustrate a board **1602** comprising multiple ICs **1604**, each IC **1604** including either the FPJ and RPJ device access architecture of FIG. 4, the FPJ Only device access architecture of FIG. 11, or the RPJ Only device access architecture of FIG. 13 to provide for a JTAG controller **404** to access FPJ and/or RPJ interfaces of embedded cores within each IC **1604** via bus **406**.

FIG. 17 is provided to illustrate an IC **1702** comprising multiple embedded cores **1704**, each embedded core **1704** including either FPJ and RPJ device access architecture of Figure, the FPJ Only device access architecture of FIG. 11, or the RPJ Only device access architecture of FIG. 13 to

provide for a JTAG controller **404** to access FPJ and/or RPJ interfaces of further embedded cores within each embedded core **1704** via bus **406**.

FIG. 18 is provided to illustrate how the FPJ and RPJ device access architecture **402** of FIG. 4 may be adapted to provide for wireless transmit **1810** and receive **1812** communication with the adapted architecture **1802** of FIG. 18 from a wireless JTAG controller **1804**. The FPJ and RPJ access architecture **1802** is the same as the FPJ and RPJ access architecture **402** of FIG. 4 with the exception that an RF transmit/receive circuit **1806** has been coupled to bus **406** of the FJP & RPJ Interface **408** to provide for wireless communication with the wireless JTAG controller **1804**. The wireless JTAG controller **1804** is the same as the JTAG controller **404** of FIG. 4 with the exception that an RF transmit/receiver circuit **1808** has been coupled to bus **406** of the JTAG controller **404** to provide the wireless communication with the RF transmit/receive circuit **1806** of FPJ and RPJ access architecture **1802**. With the exception of the wireless communication, the operation of the wireless JTAG controller **1804** and wireless FPJ and RPJ device access architecture **1802** is the same as previously described.

FIG. 19 is provided to illustrate how the FPJ Only device access architecture **1102** of FIG. 11 may be adapted to provide for wireless transmit **1810** and receive **1812** communication with the adapted architecture **1902** of FIG. 19 from a wireless JTAG controller **1804**. The FPJ Only access architecture **1902** is the same as the FPJ Only access architecture **1102** of FIG. 11 with the exception that an RF transmit/receive circuit **1806** has been coupled to bus **406** of the FPJ Only Interface **1104** to provide for wireless communication with the wireless JTAG controller **1804**. The wireless JTAG controller **1804** is the same as described in regard to FIG. 18. With the exception of the wireless communication, the operation of the wireless JTAG controller **1804** and wireless FPJ Only device access architecture **1902** is the same as previously described.

FIG. 20 is provided to illustrate how the RPJ Only device access architecture **1302** of FIG. 13 may be adapted to provide for wireless transmit **1810** and receive **1812** communication with the adapted architecture **2002** of FIG. 20 from a wireless JTAG controller **1804**. The RPJ Only access architecture **2002** is the same as the RPJ Only access architecture **1302** of FIG. 13 with the exception that an RF transmit/receive circuit **1806** has been coupled to bus **406** of the RPJ Only Interface **1304** to provide for wireless communication with the wireless JTAG controller **1804**. The wireless JTAG controller **1804** is the same as described in regard to FIG. 18. With the exception of the wireless communication, the operation of the wireless JTAG controller **1804** and wireless RPJ Only device access architecture **2002** is the same as previously described.

Various wireless JTAG access schemes are known in the art. One example of wireless JTAG access is described in a paper published in the 2004 VLSI Test Symposium proceedings by Hans Eberle, titled "Testing Systems Wirelessly," which is incorporated and referenced herein. The wireless interface circuits **1806** and **1808** for FIGS. 18, 19, and 20 could use the wireless interface described in this paper, or any other type of wireless JTAG interface.

FIG. 18 illustrates the combined use of a wireless interface and the FPJ and RPJ access architecture to wirelessly select and access FPJ and RPJ devices on a substrate.

FIG. 19 illustrates the combined use of a wireless interface and the FPJ Only access architecture to wirelessly select and access FPJ devices on a substrate.

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FIG. 20 illustrates the combined use of a wireless interface and the RPJ Only access architecture to wirelessly select and access RPJ devices on a substrate.

Although the disclosure has been described in detail, it should be understood that various changes, substitutions and alterations may be made without departing from the spirit and scope of the disclosure as defined by the appended claims.

What is claimed is:

1. A process comprising:
 - (a) transitioning interface circuitry to a reset state, the interface circuitry having:
 - a first full pin interface;
 - a second full pin interface; and
 - a third reduced pin interface;
 - (b) while in the reset state, receiving a sequence of bits on the first full pin interface; and
 - (c) in response to the received sequence of bits, switching the interface circuitry to couple the first full pin interface between one of the second full pin interface and the third reduced pin interface.
2. The process of claim 1 in which the transitioning includes moving the interface circuitry among states of at least Test Logic Reset, Run Test/Idle, Select-DR, and Select-IR states.
3. The process of claim 1 in which the transitioning interface circuitry to a reset state includes transitioning the interface circuitry to one of a Run Test/Idle state, a Pause-DR state, or a Pause-IR state.
4. The process of claim 1 in which:
 - the first full pin interface includes a test data input, a test clock input, a test mode select input, and a test data output;
 - the second full pin interface includes a test data output, a test clock output, a test mode select output, and a test data input; and
 - the third reduced pin interface has no more than two pins.
5. The process of claim 4 in which the third reduced pin interface has one pin.
6. The process of claim 1 in which the receiving a sequence of bits includes receiving a sequence of 13 bits.
7. The process of claim 1 in which the receiving a sequence of bits includes receiving a sequence of 26 bits representing 13 symbols.
8. The process of claim 1 in which the transitioning interface circuitry to a reset state includes powering up the interface circuitry.
9. The process of claim 1 including again transitioning interface circuitry to a reset state after the switching of the interface circuitry.
10. The process of claim 1 including transitioning the interface circuitry among states of Test Logic Reset, Run Test/Idle, Select-DR, and Select-I after the switching of the interface circuitry.
11. The process of claim 1 in which the receiving a sequence of bits on first full pin interface includes use of a data pin and a clock pin on the first full pin interface.
12. The process of claim 1 in which the first full pin interface further includes a Test Logic Reset pin.
13. The process of claim 12 in which activation of the Test Logic Reset pin effectuates the moving interface circuitry to a reset state.
14. The process of claim 1 in which the transitioning interface circuitry to a reset state includes receiving on the first full pin interface a test clock signal and a test mode select signal.

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15. The process of claim 1 in which the switching includes coupling test data in signals, test clock signals, test mode select signals and test data out signals from the first full pin interface to the second full pin interface.

16. The process of claim 1 in which the switching includes coupling test data in signals, test clock signals, test mode select signals and test data out signals from the first full pin interface to a third full pin interface.

17. The process of claim 1 in which the receiving includes detecting a shadow protocol from the sequence of bits received on the first full pin interface.

18. The process of claim 17 in which the receiving includes determining an address match from the sequence of bits received on the first full pin interface.

19. The process of claim 18 in which the receiving includes receiving a command to enable coupling the first full pin interface to one of the second full pin interface and the third reduced pin interface.

20. The process of claim 1 in which the transitioning includes transitioning interface circuitry having:

a shadow protocol detection circuit that includes a state machine receiving test clock signals, test mode select signals, and test data in signals from the first full pin interface;

a command circuit having inputs coupled to the protocol detection circuit and having a second full pin interface enable output and a third reduced pin interface enable output; and

an address match circuit coupled to the shadow protocol detection circuit.

21. A process comprising:

(a) transitioning interface circuitry to a reset state, the interface circuitry having:

- a first full pin interface;
- a second full pin interface; and
- a third reduced pin interface; and

(b) transitioning the interface circuitry from the reset state to enable communication between the first full pin interface and one of the second full pin interface and reduced pin interface.

22. The process of claim 21 in which the transitioning the interface circuitry from the reset state includes enabling immediate communication between the first full pin interface and second full pin interface.

23. The process of claim 21 in which the transitioning the interface circuitry from the reset state includes receiving a series of bits on the first full pin interface enabling communication between the first full pin interface and the reduced pin interface.

24. A process comprising:

(a) transitioning interface circuitry to a reset state, the interface circuitry having:

- a first full pin interface;
- a second full pin interface; and
- a third reduced pin interface; and

(b) transitioning the interface circuitry from the reset state to a non-reset state to enable communication between the first full pin interface and one of the second full pin interface and reduced pin interface.

25. The process of claim 24 in which the transitioning the interface circuitry to the non-reset state includes enabling communication between the first full pin interface and second full pin interface.

26. The process of claim 24 in which the transitioning the interface circuitry to the non-reset state includes receiving a

series of serial bits from the first full pin interface enabling communication between the first full pin interface and the reduced pin interface.

27. The process of claim 26 in which the receiving a series of bits includes receiving a data input on the first full pin interface.

28. The process of claim 26 in which the receiving a series of bits includes receiving a clock input from the first full pin interface.

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